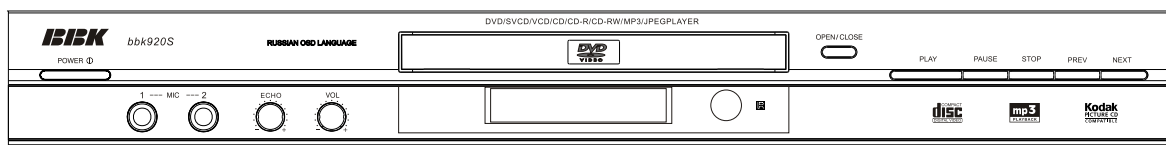


SERVICE MANUAL

Bbk920S



CONTENTS

1.	SAFETY PRECAUTIONS	1
2.	PREVENTION OF ELECTRO STATIC DISCHARGE(ESD)TO ELECTROSTATICALLY SENSITIVE(ES)DEVICES	1
3.	CONTROL BUTTON LOCATIONS AND EXPLANATIONS	2
4.	PREVENTION OF STATIC ELECTRICITY DISCHARGE	3
5.	ASSEMBLING AND DISASSEMBLING THE MECHANISM UNIT	4
5.1	OPTICAL PICKUP UNIT EXPLODED VIEW AND PART LIST	4
5.2	BRACKET EXPLODED VIEW AND PART LIST	6
5.3	MISCELLANEOUS	7
6.	ELECTRICAL CONFIRMATION	8
6.1	VIDEO OUTPUT (LUMINANCE SIGNAL) CONFIRMATION	8
6.2	VIDEO OUTPUT(CHROMINANCE SIGNAL) CONFIRMATION	9
7.	MPEG BOARD CHECK WAVEFORM	10
8.	IC BLOCK DIAGRAM & DESCRIPTION	11
8.1	MT1336	11
8.2	MT1379	19
8.3	U214 HY29F800	35
8.4	U203 SDRAM-HY57V1610D	38
9.	SCHEMATIC & PCB WIRING DIAGRAM	43
10.	SPARE PARTS LIST	56

1. SAFETY PREAUTIONS

1.1 GENERAL GUIDELINES

1. When servicing, observe the original lead dress. if a short circuit is found, replace all parts which have been overheated or damaged by the short circuit.
2. After servicing, see to it that all the protective devices such as insulation barrier, insulation papers shields are properly installed.
3. After servicing, make the following leakage current checks to prevent the customer from being exposed to shock hazards.

2.PREVENTION OF ELECTRO STATIC DISCHARGE(ESD)TO ELECTROSTATICALLY SENSITIVE(ES)DEVICES

Some semiconductor(solid state)devices can be damaged easily by static electricity. Such components commonly are called Electrostatically Sensitive(ES)Devices. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor chip components. The following techniques should be used to help reduce the incidence of component damage caused by electro static discharge(ESD).

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any ESD on your body by touching a known earth ground. Alternatively, obtain and wear a commercially availabel discharging ESD wrist strap, which should be removed for potential shock reasons prior to applying power to the unit under test.
2. After removing an electrical assembly equipped with ES devices,place the assembly on a conductive surface such as alminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static solder removal device. Some solder removal devices not classified as anti-static (ESD protected)can generate electrical charge sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, alminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.

Caution

Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.

8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity(ESD).

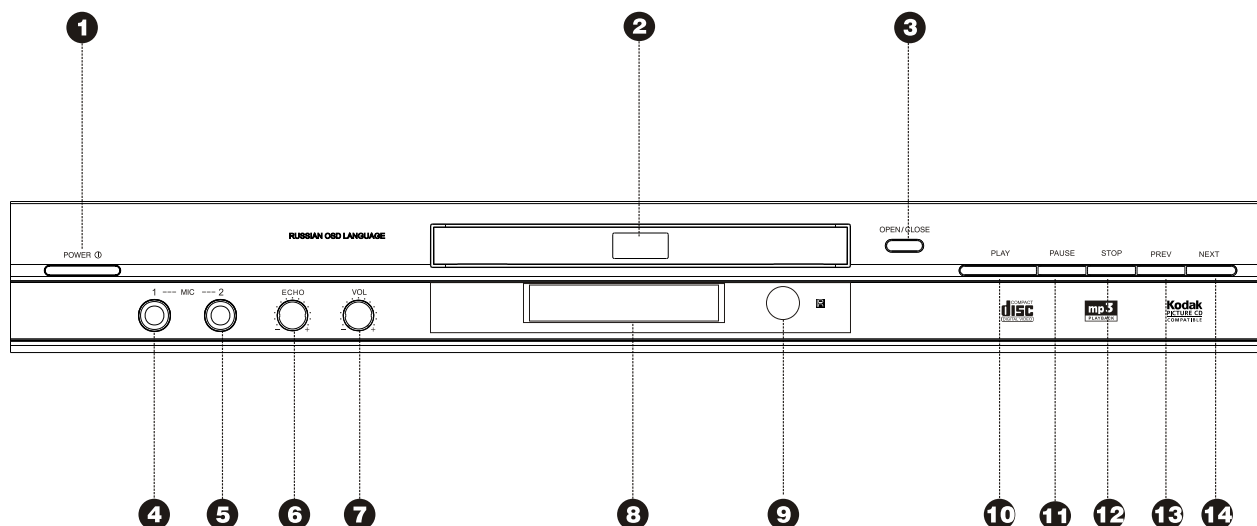
notice (1885x323x2 tiff)

IMPORTANT SAFETY NOTICE

There are special components used in this equipment which are imporant for safety. These parts are marked by $\triangle$ in the schematic diagrams, Exploded Views and replacement parts list. It is essential that these critical parts should be replaced with manufacturer's specified parts to prevent shock, fire, or other hazards. Do not modify the original design without permission of manufacturer.

Control Button Locations and Explanations

Front Panel Illustration



1 POWER switch

2 Disc tray

3 OPEN/CLOSE button

4 MIC 1 jack

5 MIC 2 jack

6 ECHO adjustment knob

7 MIC VOLUME knob

8 VFD display window

9 IR SENSOR button

10 PLAY button

11 PAUSE button

12 STOP button

13 PREV button

14 NEXT button

4. PREVENTION OF STATIC ELECTRICITY DISCHARGE

The laser diode in the traverse unit (optical pickup) may break down due to static electricity of clothes or human body. Use due caution to electrostatic breakdown when servicing and handling the laser diode.

4.1. Grounding for electrostatic breakdown prevention

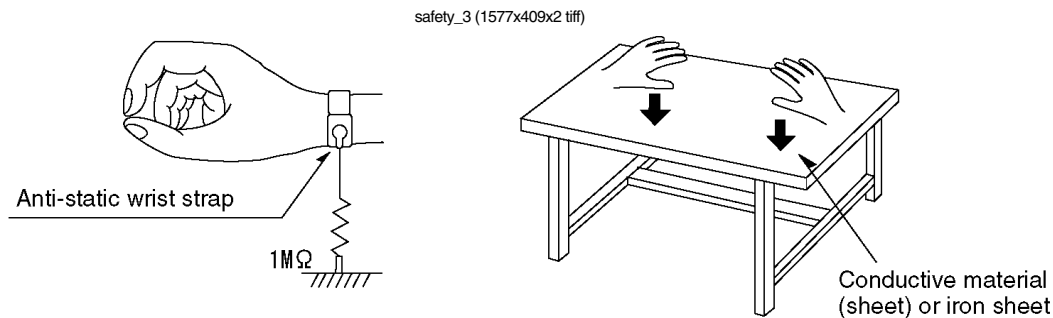
Some devices such as the DVD player use the optical pickup (laser diode) and the optical pickup will be damaged by static electricity in the working environment. Proceed servicing works under the working environment where grounding works is completed.

4.1.1. Worktable grounding

1. Put a conductive material (sheet) or iron sheet on the area where the optical pickup is placed, and ground the sheet.

4.1.2. Human body grounding

- 1 Use the anti-static wrist strap to discharge the static electricity from your body.



4.1.3. Handling of optical pickup

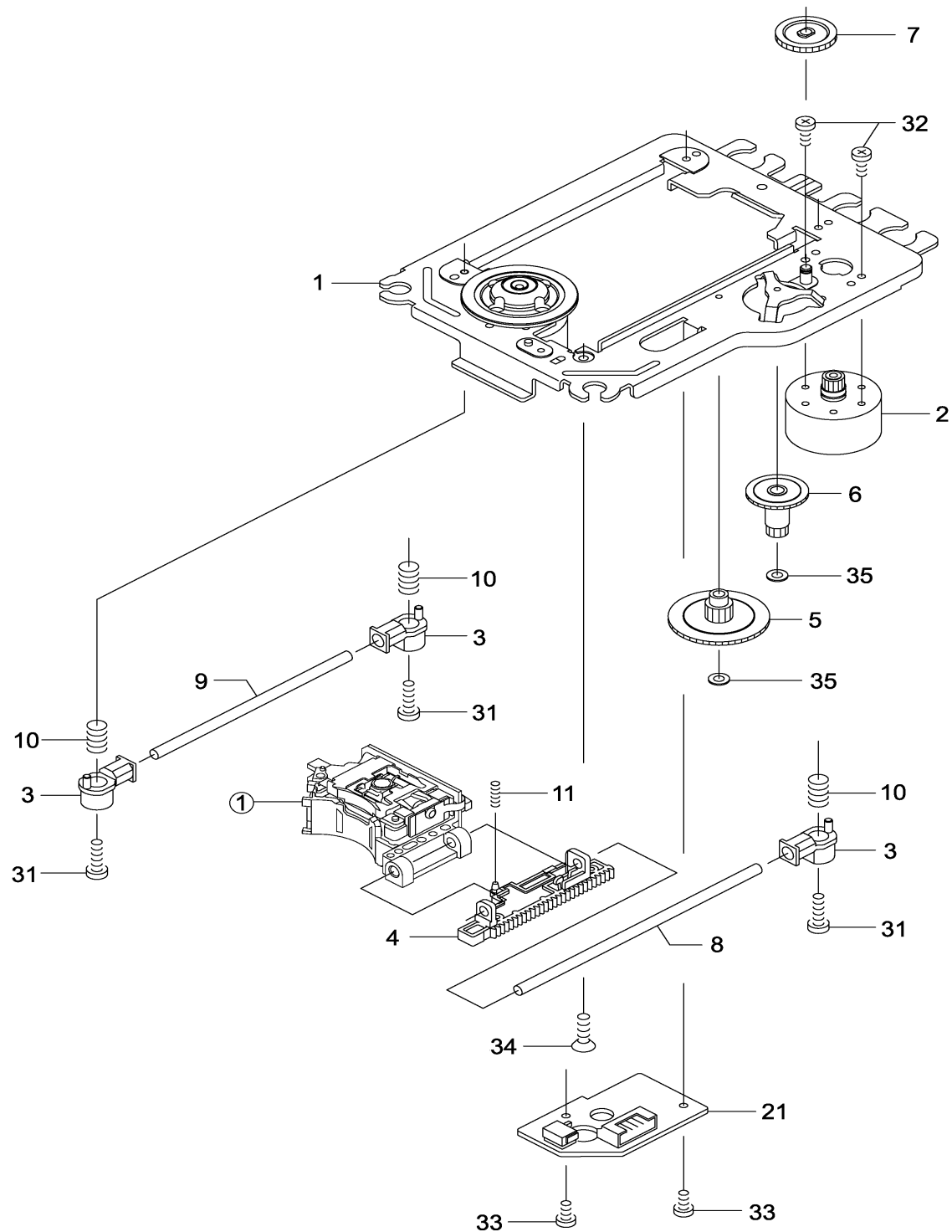
1. To keep the good quality of the optical pickup maintenance parts during transportation and before installation, the both ends of the laser diode are short-circuited. After replacing the parts with new ones, remove the short circuit according to the correct procedure. (See this Technical Guide).
2. Do not use a tester to check the laser diode for the optical pickup. Failure to do so will damage the laser diode due to the power supply in the tester.

4.2. Handling precautions for Traverse Unit (Optical Pickup)

1. Do not give a considerable shock to the traverse unit (optical pickup) as it has an extremely high-precision structure.
2. When replacing the optical pickup, install the flexible cable and cut its short lead with a nipper. See the optical pickup replacement procedure in this Technical Guide. Before replacing the traverse unit, remove the short pin for preventing static electricity and install a new unit. Connect the connector as short times as possible.
3. The flexible cable may be cut off if an excessive force is applied to it. Use caution when handling the cable.
4. The half-fixed resistor for laser power adjustment cannot be adjusted. Do not turn the resistor.

5. Assembling and disassembling the mechanism unit

5.1 Optical pickup Unit Exploded View and Part List



Pic (1)

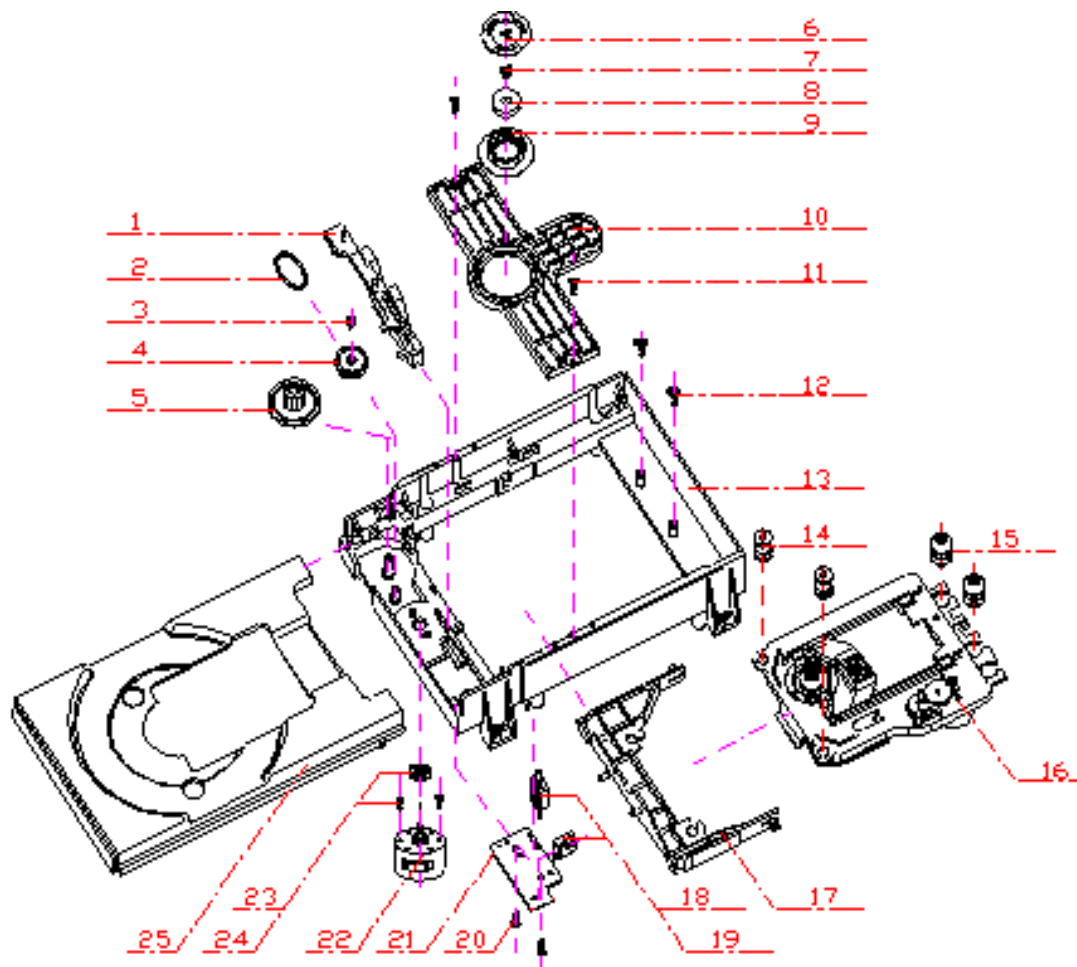
Materials to Pic (1)

No.	PARTS CODE	PARTS NAME	Q' ty
①	14692200	SF-HD60	1
1	1EA0311A06300	ASSY, CHASSIS, COMPLETE	1
2	1EA0M10A15500	ASSY, MOTOR, SLED	1
Or	1EA0M10A15501	ASSY, MOTOR, SLED	1
3	1EA2451A24700	HOLDER, SHAFT	3
4	1EA2511A29100	GEAR, RACK	1
5	1EA2511A29200	GEAR, DRIVE	1
6	1EA2511A29300	GEAR, MIDDLE, A	1
7	1EA2511A29400	GEAR, MIDDLE, B	1
8	1EA2744A03000	SHAFT, SLIDE	1
9	1EA2744A03100	SHAFT, SLIDE, SUB	1
10	1EA2812A15300	SPRING, COMP, TYOUSEI	3
11	1EA2812A15400	SPRING, COMP, RACK	1
21	1EA0B10B20100	ASSY, PWB	1
Or	1EA0B10B20200	ASSY, PWB	1
31	SEXEA25700---	SPECIAL SCREW BIN+-M2X11	3
32	SEXEA25900---	SPECIAL SCREW M1.7X2.2	2
33	SFBPN204R0SE-	SCR S-TPG PAN 2X4	2
34	SFSFN266R0SE-	SCR S-TPG FLT 2.6X6	1
35	SWXEA15400---	SPECIAL WASHER 1.8X4 X0.25	2

[illegible]

Note : This parts list is not for service parts supply.

5.2 Bracket Exploded View and Part List



Pic (2)

Materials to Pic(2)

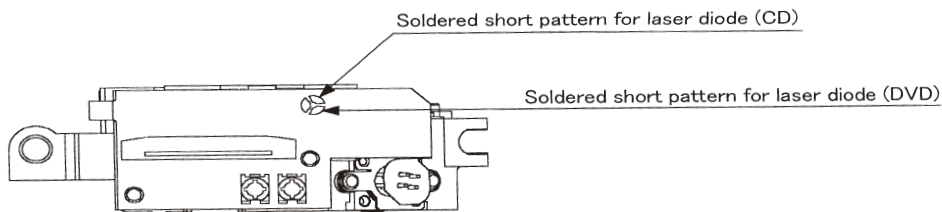
- | | |
|-----------------------------------|--------------------------|
| 1.bracket | 14. front silicon rubber |
| 2.belt | 15. Back silicon rubber |
| 3.screw | 16. Pick-up |
| 4.belt wheel | 17. Pick-up |
| 5.gearwheel | 18. switch |
| 6.iron chip | 19. Five-pin flat plug |
| 7. Immobility mechanism equipment | 20. screw |
| 8. Magnet | 21. PCB |
| 9. Platen | 22. motor |
| 10. Bridge bracket | 23. Motor wheel |
| 11. screw | 24. screw |
| 12. screw | 25.tray |
| 13. Big bracket | |

Before going process with disassembly and installation, please carefully both peruse the chart and confirm the materials.

5.3 MISCELLANEOUS

5.3.1 Protection of the LD(Laser diode)

Short the parts of LD circuit pattern by soldering.



5.3.2 Cautions on assembly and adjustment

Make sure that the workbenches, jigs, tips, tips of soldering irons and measuring instruments are grounded, and that personnel wear wrist straps for ground.

Open the LD short lands quickly with a soldering iron after a circuit is connected.

Keep the power source of the pick-up protected from internal and external sources of electrical noise.

Refrain from operation and storage in atmospheres containing corrosive gases (such as H_2S , SO_2 , NO_2 and Cl_2) or toxic gases or in locations containing substances (especially from the organic silicon, cyan, formalin and phenol groups) which emit toxic gases. It is particularly important to ensure that none of the above substances are present inside the unit. Otherwise, the motor may no longer run.

6.Electrical Confirmation

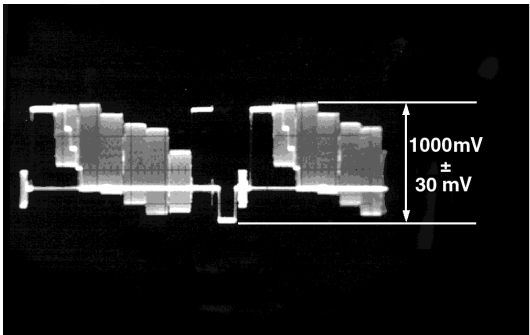
6.1. Video Output (Luminance Signal) Confirmation

DO this confirmation after replacing a P.C.B.

Measurement point	Mode	Disc
Video output terminal	Color bar 75% PLAY(Title 46):DVDT-S15 PLAY(Title 12):DVDT-S01	DVDT-S15 or DVDT-S01
Measuring equipment,tools	Confirmation value	
200mV/dir,10 μ sec/dir	1000mVp-p±30mV	

Purpose:To maintain video signal output compatibility.

- 1.Connect the oscilloscope to the video output terminal and terminate at 75 ohms.
- 2.Confirm that luminance signal(Y+S)level is 1000mVp-p±30mV



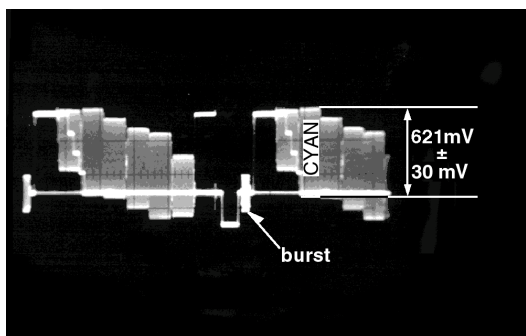
6.2 Video Output(Chrominance Signal) Confirmation

Do the confirmation after replacing P.C.B.

Measurement point	Mode	Disc
Video output terminal	Color bar 75% PLAY(Title 46):DVDT-S15 PLAY(Title 12):DVDT-S01	DVDT-S15 or DVDT-S01
Measuring equipment,tools	Confirmation value	
Screwdriver,Oscilloscope 200mV/dir,10 μ sec/dir	621mVp-p $\pm$ 30mV	

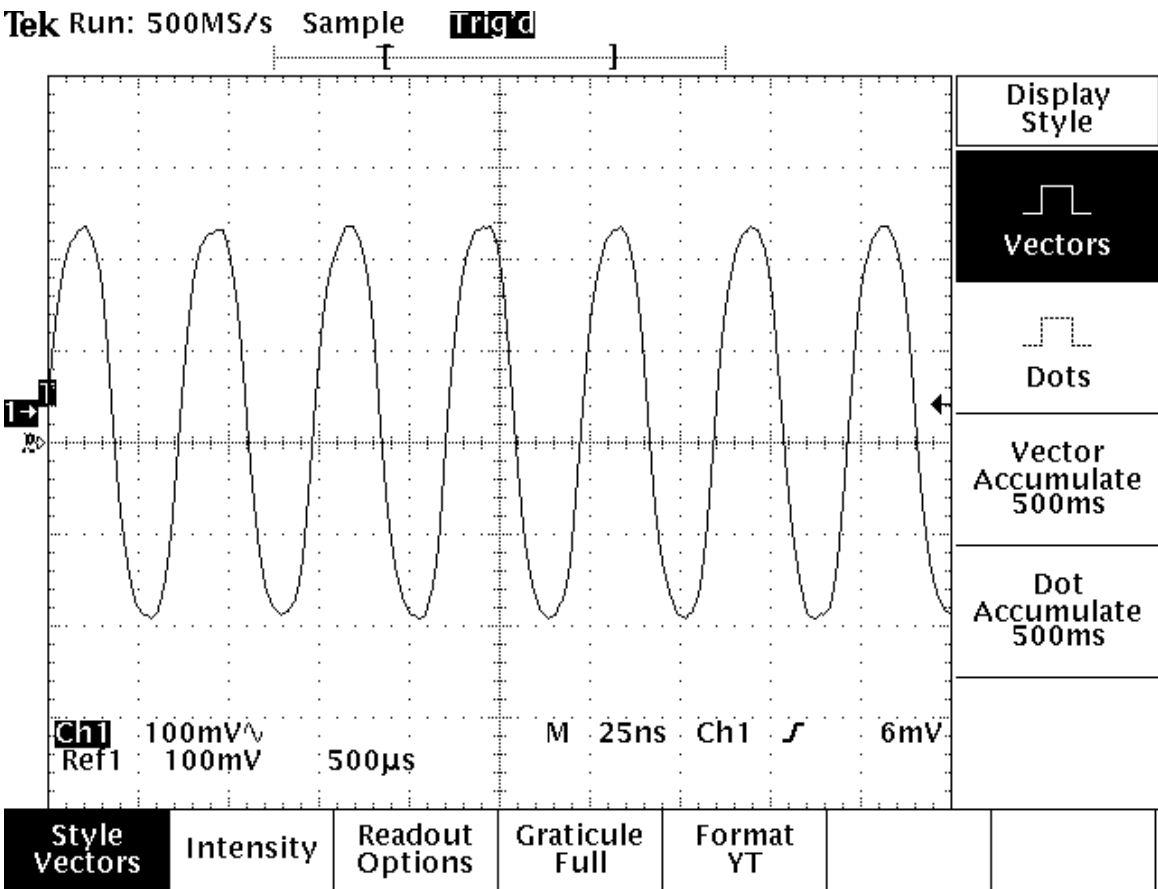
Purpose:To maintain video signal output compatibility.

- 1.Connect the oscilloscope to the video output terminal and terminate at 75 ohme.
- 2.Confirm that the chrominance signal(C)level is 621 mVp-p $\pm$ 30mV

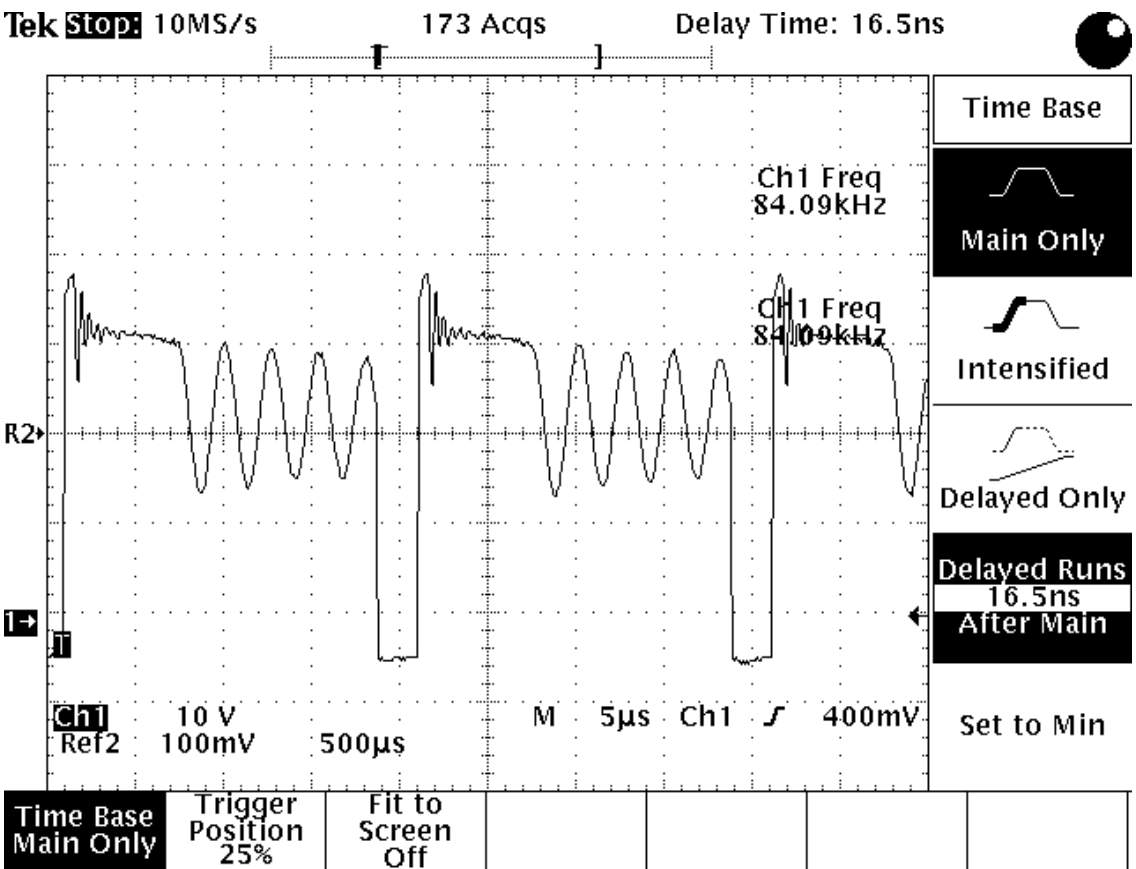


7.MPEG BOARD CHECK WAVEFORM

7.1 27MHz WAVEFORM



7.2 IC5L0380R PIN.2 WAVEFORM DIAGRAM



8. IC BLOCK DIAGRAM & DESCRIPTION

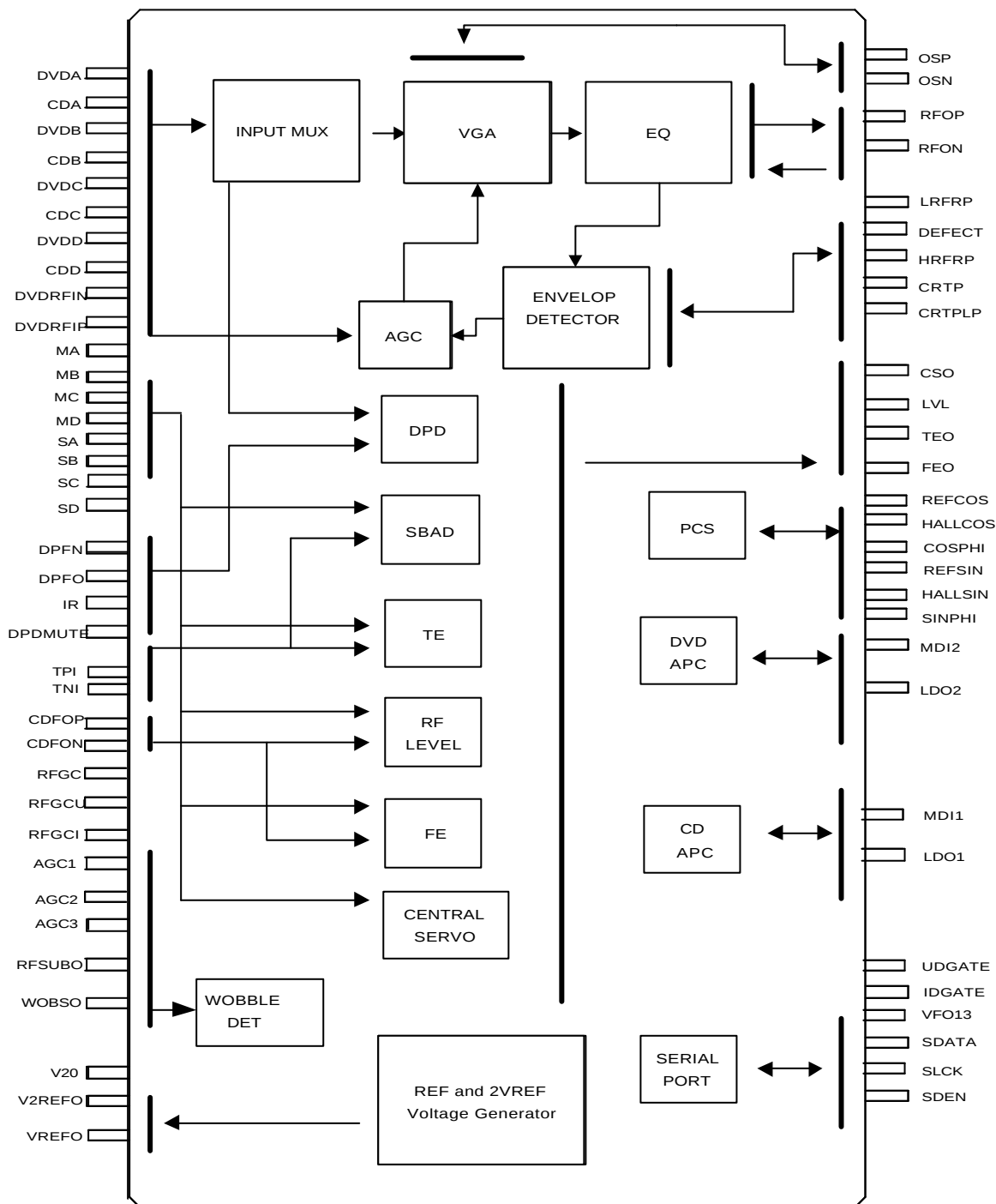
8.1 MT1336

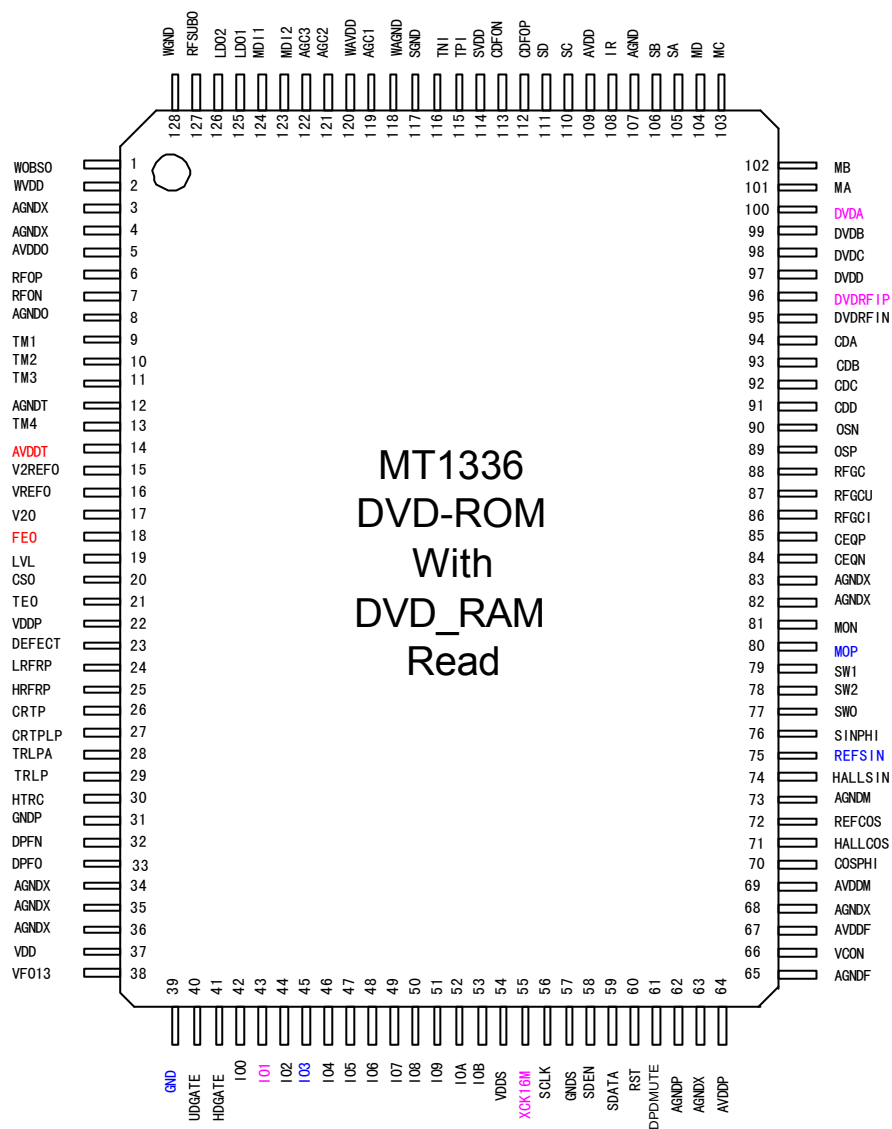
GENERAL DESCRIPTION

MT1336 is a high performance CMOS analog front-end IC for both CD-ROM driver up to 48XS and DVD-ROM driver up to 16XS. It also supports DVD-RAM read up to 4XS Version 2. It contains servo amplifiers to generate focusing error, 3-beam tracking error, 1 beam radial push-pull signal, RF level and SBAD for servo functions. It also includes DPD tracking error signal for DVD-ROM application. For DVD-RAM disks, there are also Differential Push-Pull (DPP) method for generating tracking signal and Differential Astigmatic Detection (DAD) for processing focusing signal. Programmable equalizer and AGC circuits are also incorporated in this chip to optimize read channel performance. In addition, this chip has dual automatic laser power control circuits for DVD-ROM (DVD-RAM) and CD-ROM separately and reference voltage generators to reduce external components. Programmable functions are implemented by the access of internal register through bi-directional serial port to configure modes selection.

FEATURES

- RF equalizer with programmable f_c from 3MHz to 70 MHz and programmable boost from 3dB to 13dB.
- MT1336 supports at least eight different kinds of pick-up heads with versatile input configuration for both RF input stages and servo signal blocks.
- Versatile on-line AGC.
- 3 beams tracking error signal generator for CD-ROM application.
- One beam differential phase tracking error (DPD) generator for DVD-ROM application.
- Differential push pull tracking error (DPP) generator for DVD-RAM application.
- Focusing error signal generator for CD-ROM, DVD-ROM and DVD-RAM (DAD method).
- RF level signal generator.
- Sub-beam added signal for 3 beams CD-ROM.
- One beam push-pull signal generator for central servo application.
- High speed RF envelop detection circuit with bandwidth up to 400KHz for CD-ROM.
- Defect and Blank detection circuits.
- Dual automatic laser power control circuits with programmable level of LD monitor voltage.
- Vref=1.4V voltage and V2ref=2.8V voltage generators.
- V20=2.0V voltage for pick-up head reference.
- Bi-directional serial port to access internal registers.


MT1336 FUNCTION BLOCKS DIAGRAM



MT1336 PIN ASSIGNMENT


MT1336 PIN DESCRIPTIONS

Pin Numbers	Symbol	Type	Description
LQFP128			
RF Flag Interface			
23	DETECT	Digital Output	Flag of bad data output status
RF SIO interface			
56	SCLK	Digital Input	RF serial clock input
58	SDEN	Digital Input	RF serial data enable
59	SDATA	Digital IO	RF serial data IO
60	RST	Digital input	Reset (active high)
55	XCK16M	Digital Input	16.9MHz for verification
RF SERVO interface			
40	UDGATE	Digital Input	Control signal for DVD-RAM
41	IDGATE	Digital Input	Control signal for DVD-RAM
38	VFO13	Digital Input	DVD -RAM Header signal
RF			
100	DVDA	Analog input	AC coupled DVD RF signal input A
99	DVDB	Analog Input	AC coupled DVD RF signal input B
98	DVDC	Analog Input	AC coupled DVD RF signal input C
97	DVDD	Analog Input	AC coupled DVD RF signal input D
95	DVDRFIN	Analog Input	AC coupled DVD RF signal input RFIN
96	DVDRFIP	Analog Input	AC coupled DVD RF signal input RFIP
94	CDA	Analog Input	AC coupled CD RF signal input A
93	CDB	Analog Input	AC coupled CD RF signal input B
92	CDC	Analog Input	AC coupled CD RF signal input C
91	CDD	Analog Input	AC coupled CD RF signal input D
90	OSN	Analog	RF Offset cancellation capacitor connecting
89	OSP	Analog	RF Offset cancellation capacitor connecting
85	CEQP	Analog	RF Offset cancellation capacitor connecting
84	CEQN	Analog	RF Offset cancellation capacitor connecting
88	RFGC	Analog	RF AGC loop capacitor connecting for DVD -ROM



87	RFGCU	Analog	RF AGC loop capacitor connecting for DVD -RAM
86	RFGCI	Analog	RF AGC loop capacitor connecting for DVD -RAM
101	MA	Analog Input	DC coupled DVD-RAM main-beam RF signal input A
102	MB	Analog Input	DC coupled DVD-RAM main-beam RF signal input B
103	MC	Analog Input	DC coupled DVD-RAM main-beam RF signal input C
104	MD	Analog Input	DC coupled DVD-RAM main-beam RF signal input D
105	SA	Analog Input	DC coupled DVD-RAM sub-beam RF signal input A
106	SB	Analog Input	DC coupled DVD-RAM sub-beam RF signal input B
110	SC	Analog Input	DC coupled DVD-RAM sub-beam RF signal input C
111	SD	Analog Input	DC coupled DVD-RAM sub-beam RF signal input D
108	IR	Analog	External current bias resistor (R=20K)
119	AGC1	Analog	Wobble AGC loop1 capacitor
121	AGC2	Analog	Wobble AGC loop2 capacitor
122	AGC3	Analog	Wobble AGC loop3 capacitor
127	RFSUBO	Analog output	Header push-pull RF output signal
1	WOBSO	Digital output	Wobble signal output
6	RFOP	Analog output	RF positive output
7	RFON	Analog output	RF negative output
TRACKING ERROR			
32	DPFN	Analog	DPD amplifier negative input
33	DPFO	Analog	DPD amplifier output
61	DPDMUTE	Digital input	DPD mute control input
116	TNI	Analog Input	3 beam satellite PD signal negative input
115	TPI	Analog Input	3 beam satellite PD signal positive input
21	TEO	Analog Output	Tracking error output
FOCUSING ERROR & RF LEVEL & CENTRAL SERVO SIGNAL			
112	CDFOP	Analog Input	CD focusing error positive input
113	CDFON	Analog Input	CD focusing error negative input
18	FEO	Analog Output	Focusing error output
19	LVL	Analog Output	RF level output
20	CSO	Analog output	Central servo signal output
ALPC			

124	MDI1	Analog Input	Laser power monitor input
125	LDO1	Analog Output	Laser driver output
123	MDI2	Analog Input	Laser power monitor input
126	LDO2	Analog Output	Laser driver output
RF RIPPLE			
26	CRTP	Analog	RF top envelop filter capacitor connecting
27	CRTPLP	Analog	Defect level filter capacitor connecting
25	HRFRP	Analog output	High frequency RF ripple output or Blank detector' s output
24	LRFRP	Analog output	Low frequency RF ripple output
POWER			
67, 69	AVDD	Power	Master PLL Filter power
65, 73	AGND	GND	GND for Master PLL Filter
64	AVDD	Power	DPD Power
62	AGND	GND	DPD GND
109	AVDD	Power	RF path Power
107	AGND	GND	RF path GND
114	SVDD	Power	Servo Power
117	SGND	GND	Servo GND
2,120	WAVDD	Power	Wobble Power
128,118	WAGND	GND	Wobble GND
5	AVDDO	Power	Power for RF output
8	AGNDO	GND	GND for RF output
14	AVDDT	Power	Power for Trimming PAD
12	AGNDT	GND	GND for Trimming PAD
22	VDDP	Power	Peak Detection Power
31	GNDP	GND	Peak Detection GND
37,54	VDD	Power	Serial I/O Power
39,57	GND	GND	Serial I/O GND
REFERENCE VOLTAGE			
16	VREFO	Analog output	Reference voltage 1.4V
15	V2REFO	Analog output	Reference voltage 2.8V
17	V20	Analog Output	Reference voltage 2.0V

ALPC TRIMMING			
9	TM1	Analog input	Trimming pin for ALPC1
10	TM2	Analog input	Trimming pin for ALPC1
11	TM3	Analog input	Trimming pin for ALPC2
13	TM4	Analog input	Trimming pin for ALPC2
HIGH SPEED TRACK COUNTING			
29	TRLP	Analog	Low-pass filter capacitor connecting
28	TRLPA	Analog	Low-pass filter capacitor connecting
30	HTRC	Digital output	High speed track counting digital output
PCS			
74	HALLSIN	Analog input	Negative input of amplifier for hall sensor signal
75	REFSIN	Analog input	Positive input of amplifier for hall sensor signal
76	SINPHI	Analog output	Amplifier output for hall sensor signal
71	HALLCOS	Analog input	Negative input of amplifier for hall sensor signal
72	REFCOS	Analog input	Positive input of amplifier for hall sensor signal
70	COSPHI	Analog output	Amplifier output for hall sensor signal
FOR MONITOR ONLY			
81	MON	Analog output	
80	MOP	Analog output	
66	VCON	Analog output	
77	SWO	Analog output	Output from mux of SW1 & SW2
78	SW2	Analog input	External input for servo input select
79	SW1	Analog input	External input for servo input select
FOR SERIAL I/O			
42	IO0		
43	IO1		
44	IO2		
45	IO3		
46	IO4		
47	IO5		

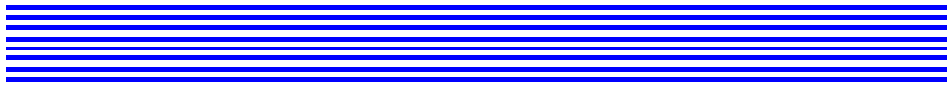


MT1336

PRELIMINARY, SUBJECT TO CHANGE WITHOUT NOTICE

MTK CONFIDENTIAL, NO DISCLOSURE

48	IO6		
49	IO7		
50	IO8		
51	IO9		
52	IOA		
53	IOB		



MT1379

Specifications are subject to change without notice

Progressive Scan DVD Player Combo Chip

8.2 MT1379

- Super Integration DVD player single chip
 - Servo controller and data channel processing
 - MPEG-1/MPEG-2/JPEG video decoding
 - Dolby AC-3/DTS/DVD-Audio audio decoding
 - Unified track buffer and A/V decoding buffer
 - Video processing for scaling and video quality enhancement
 - OSD & Sub-picture decoding
 - Built-in clock generator
 - Built-in TV encoder
 - Built-in progressive video output
 - Video input port and audio/SPDIF input port
- Speed Performance on Servo and Decoding
 - DVD-ROM up to 8XS
 - CD-ROM up to 24XS
 - Built-in a frequency programmable clock to μ P and RSPC Decoder to optimize the performance over power
- Channel Data Processor
 - Provides interface with analog front-end processor
 - Analog data slicer for small jitter capability
 - Built-in high performance data PLL for channel data demodulation
 - EFM/EFM+ data demodulation
 - Enhanced channel data frame sync protection & DVD-ROM sector sync protection
- Servo Control and Spindle Motor Control
 - Programmable frequency error gain and phase error gain of spindle PLL to control spindle motor on CLV and CAV mode
 - Provide a varipitch speed control for CLV and CAV mode
 - Built-in ADCs and DACs for digital servo control
 - Provide 2 general PWM
- Tray control can be PWM output or digital output
 - Built-in DSP for digital servo control
- Host Micro controller
 - Built-in 8032 micro controller
 - Built-in internal 373 and 8-bit programmable lower address port
 - 1024-bytes on-chip RAM
 - Up to 2M bytes FLASH-programming interface
 - Supports 5/3.3-Volt. FLASH interface
 - Supports power-down mode
 - Supports additional serial port
- DVD-ROM/CD-ROM Decoding Logic
 - Supports CD-ROM Mode 1, CD-ROM XA Mode 2 Form 1, CD-ROM XA Mode 2 Form 2, and CD-DA formats
 - High-speed ECC logic capable of correcting one error per each P-codeword or Q-codeword
 - Automatic sector Mode and Form detection
 - Automatic sector Header verification
 - 8-bit counter for decode completion check
 - Programmable descrambling and error correction schemes
 - Automatically repeated error corrections
 - 8-bit C2 Pointer counter
 - Decoder Error Notification Interrupt that signals various decoder errors
 - Provide error correction acceleration
- Buffer Memory Controller
 - Supports 16Mb/32Mb/64Mb/128Mb SDRAM
 - Supports 16-bit/32-bit SDRAM data bus interface
 - Build in a DRAM interface programmable clock to optimize the DRAM performance
 - Provide the self-refresh mode SDRAM
 - Programmable DRAM access cycle and refresh

- cycle timings
 - Block-based sector addressing
 - Programmable buffering counter for buffer status tracking
 - Maximum DRAM speed is 133MHz
 - Support 5/3.3-Volt. DRAM Interface
- Video Decode
 - Decodes MPEG1 video and MPEG2 main level, main profile video (720/480 and 720x576)
 - Maximum input bit-rate of 15Mbps/sec
 - Smooth digest view function with I, P and B picture decoding
 - Baseline, extended-sequential and progressive JPEG image decoding
 - RLE and non-RLE BMP image decoding
 - Support CD-G titles
- Video/OSD/SPU/HLI Processor
 - Arbitrary ratio vertical/horizontal scaling of video, from 0.25X to 256X
 - 65535/256/16/4/2-color bitmap format OSD,
 - 256/16 color RLC format OSD
 - Automatic scrolling of OSD image
 - Provides 4 -color/32x32-pixel hardware cursor
 - Fade-in, Fade out, and Wipe functions as specified in the DVD-Audio Specification and other slide show transition effects
 - Progressive scan output
- Audio Processing
 - Decoder format supports:
 - Dolby Digital (AC -3) decoding
 - DTS decoding
 - MLP decoding for DVD -Audio
 - MPEG-1 layer 1/layer 2 audio decoding
 - MPEG-2 layer1/layer2 2 -channel audio decoding
 - Dolby Pro Logic decoding
 - High Definition Compatible Digital (HDCD) decoding
 - Up to 6 channel linear PCM output for DVD Audio / DVD Video
- Downmix function
 - Support IEC 60958/61937 output
 - PCM / bit stream / mute mode
 - Custom IEC latency up to 2 frames
 - Pink noise and white noise generator
 - Karaoke functions
 - Microphone echo with adjustable echo level, echo -depth and delay length
 - Microphone tone control with three custom second-order IIR filter
 - Vocal mute/vocal assistant
 - Key shift up to +/- 8 keys controlled by 1/2 key
 - Channel equalizer
 - 3D surround processing include virtual surround and speaker separation
 - Power-down control
 - HDCD certified
- TV Encoder
 - Six 54MHz/12bit DA converters
 - Support NTSC, PAL-BDGHl, PAL-N, PAL-M interlace TV format and 480p, 576p progressive TV format
 - Automatically turn off unconnected channel(s).
 - Support PC monitor (VGA)
 - Support Macrovision 7.1
- Progressive Output
 - Automatic detect film or video source
 - 3:2 pull down source detection
 - Advanced Motion adaptive de-interlace
 - Minimum external memory requirement
- Audio/Video Output
 - Line-in/SPDIF-in for versatile audio processing
 - CCIR601/656 video input port
 - Support picture-in-picture for video decoding and input source
- Outline
 - 216-pin LQFP package
 - 3.3/2.5-Volt. Dual operating voltages

PIN DEFINITIONS

Pin Number	Symbol	Type	Description
1	IREF	Analog Input	Current reference input. It generates reference current for data PLL. Connect an external 100K resistor to this pin and PLLVSS.
2	PLLVSS	Ground	Ground pin for data PLL and related analog circuitry
3	LPIOP	Analog Output	Positive output of the low pass filter
4	LPION	Analog Output	Negative output of the low pass filter
5	LPFON	Analog output	Negative output of loop filter amplifier
6	LPFIP	Analog Input	Positive input of loop filter amplifier
7	LPFIN	Analog Input	Negative input of loop filter amplifier
8	LPFOP	Analog Output	Positive output of loop filter amplifier
9	JITFO	Analog Output	RF jitter meter output
10	JITFN	Analog Input	Negative input of the operation amplifier for RF jitter meter
11	PLLVDD3	Power	3.3V power pin for data PLL and related analog circuitry
12	FOO	Analog Output	Focus servo output. PDM output of focus servo compensator
13	TRO	Analog Output	Tracking servo output. PDM output of tracking servo compensator
14	TROPENPWM	Analog Output	Tray open output, controlled by microcontroller. This is PWM output for TRWMEN27hRW2=1 or is digital output for TRWMEN27hRW2=0
15	PWMOUT1	Analog Output	The 1st general PWM output
16	PWMOUT2	Analog Output	The 2nd general PWM output
17	DVDD2	Power	2.5V power pin for internal fully digital circuitry
18	DMO	Analog Output	Disk motor control output. PWM output
19	FMO	Analog Output	Feed motor control. PWM output
20	DVSS	Ground	Ground pin for internal fully digital circuitry
21	FG	Input	Motor Hall sensor input
22	HIGHA0	Inout 2~16MA, SR PU	Microcontroller address 8
23	HIGHA1	Inout 2~16MA, SR PU	Microcontroller address 9
24	HIGHA2	Inout 2~16MA, SR PU	Microcontroller address 10
25	HIGHA3	Inout 2~16MA, SR PU	Microcontroller address 11
26	HIGHA4	Inout 2~16MA, SR PU	Microcontroller address 12
27	HIGHA5	Inout 2~16MA, SR PU	Microcontroller address 13
28	DVSS	Ground	Ground pin for internal digital circuitry

Pin Number	Symbol	Type	Description
29	HIGHA6	Inout 2~16MA, SR PU	Microcontroller address 14
30	HIGHA7	Inout 2~16MA, SR PU	Microcontroller address 15
31	AD7	Inout 2~16MA, SR	Microcontroller address/data 7
32	AD6	Inout 2~16MA, SR	Microcontroller address/data 6
33	AD5	Inout 2~16MA, SR	Microcontroller address/data 5
34	AD4	Inout 2~16MA, SR	Microcontroller address/data 4
35	DVDD3	Power	3.3V power pin for internal digital circuitry
36	AD3	Inout 2~16MA, SR	Microcontroller address/data 3
37	AD2	Inout 2~16MA, SR	Microcontroller address/data 2
38	AD1	Inout 2~16MA, SR	Microcontroller address/data 1
39	AD0	Inout 2~16MA, SR	Microcontroller address/data 0
40	IOA0	Inout 2~16MA, SR PU	Microcontroller address 0 / IO
41	IOA1	Inout 2~16MA, SR PU	Microcontroller address 1 / IO
42	DVDD2	Power	2.5V power pin for internal digital circuitry
43	IOA2	Inout 2~16MA, SR PU	Microcontroller address 2 / IO
44	IOA3	Inout 2~16MA, SR PU	Microcontroller address 3 / IO
45	IOA4	Inout 2~16MA, SR PU	Microcontroller address 4 / IO
46	IOA5	Inout 2~16MA, SR PU	Microcontroller address 5 / IO
47	IOA6	Inout 2~16MA, SR PU	Microcontroller address 6 / IO

Pin Number	Symbol	Type	Description
48	IOA7	Inout 2~16MA, SR PU	Microcontroller address 7 / IO
49	A16	Output 2~16MA, SR	Flash address 16
50	A17	Output 2~16MA, SR	Flash address 17
51	IOA18	Inout 2~16MA, SR SMT	Flash address 18 / IO
52	IOA19	Inout 2~16MA, SR SMT	Flash address 19 / IO
53	IOA20	Inout 2~16MA, SR SMT	Flash address 20 / IO OR Videoin Data PortB 0
54	APLLVSS	Ground	Ground pin for audio clock circuitry
55	APLLVDD3	Power	3.3V Power pin for audio clock circuitry
56	ALE	Inout 2~16MA, SR PU, SMT	Microcontroller address latch enable
57	IOOE#	Inout 2~16MA, SR SMT	Flash output enable, active low / IO
58	IOWR#	Inout 2~16MA, SR SMT	Flash write enable, active low / IO
59	IOCS#	Inout 2~16MA, SR PU, SMT	Flash chip select, active low / IO
60	DVSS	Ground	Ground pin for internal digital circuitry
61	UP1_2	Inout 4MA, SR PU, SMT	Microcontroller port 1 -2
62	UP1_3	Inout 4MA, SR PU, SMT	Microcontroller port 1 -3
63	UP1_4	Inout 4MA, SR PU, SMT	Microcontroller port 1 -4
64	UP1_5	Inout 4MA, SR PU, SMT	Microcontroller port 1 -5
65	UP1_6	Inout 4MA, SR PU, SMT	Microcontroller port 1 -6
66	DVDD3	Power	3.3V power pin for internal digital circuitry

Pin Number	Symbol	Type	Description
67	UP1_7	Inout 4MA, SR PU, SMT	Microcontroller port 1 -7
68	UP3_0	Inout 4MA, SR PU, SMT	Microcontroller port 3 -0
69	UP3_1	Inout 4MA, SR PU, SMT	Microcontroller port 3 -1
70	INT0#	Inout 2~16MA, SR PU, SMT	Microcontroller interrupt 0, active low
71	IR	Input SMT	IR control signal input
72	DVDD2	Power	2.5V power pin for internal digital circuitry
73	UP3_4	Inout	Microcontroller port 3 -4
74	UP3_5	Inout	Microcontroller port 3 -5
75	UWR#	Inout 2~16MA, SR PU, SMT	Microcontroller write strobe, active low
76	URD#	Inout 2~16MA, SR PU, SMT	Microcontroller read strobe, active low
77	DVSS	Ground	Ground pin for internal digital circuitry
78	RD7	Inout	DRAM data 7
79	RD6	Inout	DRAM data 6
80	RD5	Inout	DRAM data 5
81	RD4	Inout	DRAM data 4
82	DVDD2	Power	2.5V power pin for internal digital circuitry
83	RD3	Inout	DRAM data 3
84	RD2	Inout	DRAM data 2
85	RD1	Inout	DRAM data 1
86	RD0	Inout	DRAM data 0
87	RWE#	Output 2~16MA, SR	DRAM Write enable, active low
88	CAS#	Output 2~16MA, SR	DRAM columnaddress strobe, active low
89	RAS#	Output 2~16MA, SR	DRAM row address strobe, active low
90	RCS#	Output 2~16MA, SR	DRAM chip select, active low
91	BA0	Output 2~16MA, SR	DRAM bank address 0
92	DVSS	Ground	Ground pin for internal digital circuitry
93	RD15	Inout 2~16MA, SR PU/PD, SMT	DRAM data 15

Pin Number	Symbol	Type	Description
94	RD14	Inout 2~16MA, SR PU/PD, SMT	DRAM data 14
95	RD13	Inout 2~16MA, SR PU/PD, SMT	DRAM data 13
96	RD12	Inout 2~16MA, SR PU/PD, SMT	DRAM data 12
97	DVDD3	Power	3.3V power pin for internal digital circuitry
98	RD11	Inout 2~16MA, SR PU/PD, SMT	DRAM data 11
99	RD10	Inout 2~16MA, SR PU/PD, SMT	DRAM data 10
100	RD9	Inout 2~16MA, SR PU/PD, SMT	DRAM data 9
101	RD8	Inout 2~16MA, SR PU/PD, SMT	DRAM data 8
102	DVSS	Ground	Ground pin for internal digital circuitry
103	CLK	Output 2~16MA, SR	DRAM clock
104	CLE	Output 2~16MA, SR	DRAM clock enable
105	RA11	Output 2~16MA, SR	DRAM address bit 11 or audio serial data 3 (channel 7/8)
106	RA9	Output 2~16MA, SR	DRAM address 9
107	RA8	Output 2~16MA, SR	DRAM address 8
108	DMVDD3	Power	3.3V Power pin for DRAM clock circuitry
109	DMVSS	Ground	Ground pin for DRAM clock circuitry
110	RA7	Output 2~16MA, SR	DRAM address 7
111	DVDD3	Power	3.3V power pin for internal digital circuitry
112	RA6	Output 2~16MA, SR	DRAM address 6
113	RA5	Output 2~16MA, SR	DRAM address 5
114	RA4	Output 2~16MA, SR	DRAM address 4
115	DVSS	Ground	Ground pin for internal digital circuitry
116	DQM1	Output 2~16MA, SR	Mask for DRAM input/output byte 1

Pin Number	Symbol	Type	Description
117	DQM0	Output 2~16MA, SR	Mask for DRAM input/output byte 0
118	BA1	Output 2~16MA, SR	DRAM bank address 0
119	RA10	Output 2~16MA, SR	DRAM address10
120	DVDD2	Power	2.5V power pin for internal digital circuitry
121	RA0	Output 2~16MA, SR	DRAM address 0
122	RA1	Output 2~16MA, SR	DRAM address 1
123	RA2	Output 2~16MA, SR	DRAM address 2
124	RA3	Output 2~16MA, SR	DRAM address 3
125	DVSS	Ground	Ground pin for internal digital circuitry
126	RD31	Inout 2~16MA, SR PU/PD, SMT	DRAM data 31
127	RD30	Inout 2~16MA, SR PU/PD, SMT	DRAM data 30
128	RD29	Inout 2~16MA, SR PU/PD, SMT	DRAM data 29
129	RD28	Inout 2~16MA, SR PU/PD, SMT	DRAM data 28
130	DVDD3	Power	3.3V power pin for internal digital circuitry
131	RD27	Inout 2~16MA, SR PU/PD, SMT	DRAM data 27
132	RD26	Inout 2~16MA, SR PU/PD, SMT	DRAM data 26
133	RD25	Inout 2~16MA, SR PU/PD, SMT	DRAM data 25
134	RD24	Inout 2~16MA, SR PU/PD, SMT	DRAM data 24
135	DVSS	Ground	Ground pin for internal digital circuitry
136	DQM3	Output 2~16MA, SR	Mask for DRAM input/output byte 3
137	DQM2	Output 2~16MA, SR	Mask for DRAM input/output byte 2

Pin Number	Symbol	Type	Description
138	RD23	Inout 2~16MA, SR PU/PD, SMT	DRAM data 23 / Videoin Data PortA 7
139	RD22	Inout 2~16MA, SR PU/PD, SMT	DRAM data 22 / Videoin Data PortA 6
140	DVDD2	Power	2.5V power pin for internal digital circuitry
141	RD21	Inout 2~16MA, SR PU/PD, SMT	DRAM data 21 / Videoin Data PortA 5
142	RD20	Inout 2~16MA, SR PU/PD, SMT	DRAM data 20 / Videoin Data PortA 4
143	RD19	Inout 2~16MA, SR PU/PD, SMT	DRAM data 19 / Videoin Data PortA 3
144	RD18	Inout 2~16MA, SR PU/PD, SMT	DRAM data 18 / Videoin Data PortA 2
145	DVSS	Ground	Ground pin for internal digital circuitry
146	RD17	Inout 2~16MA, SR PU/PD, SMT	DRAM data 17 / Videoin Data PortA 1
147	RD16	Inout 2~16MA, SR PU/PD, SMT	DRAM data 16 / Videoin Data PortA 0
148	ABCK	Output 4MA	Audio bit clock
149	ALRCK	Inout 4MA, PD, SMT	(1) Audio left/right channel clock (2) Trap value in power-on reset : 1 : use external 373 0: use internal 373
150	DVDD3	Power	3.3V power pin for internal digital circuitry
151	ACLK	Inout 4MA	Audio DAC master clock (384/256 audio sample frequency)
152	MC_DATA	Input	Microphone serial input
153	SPDIF	Output 2~16MA, SR : ON/OFF	SPDIF output
154	ASDATA0	Inout 4MA PD SMT	(1) Audio serial data 0 (left/right channel) (2) Trap value in power-on reset : 1 : manufactory test mode 0 : normal operation
155	ASDATA1	Inout 4MA PD SMT	(1) Audio serial data 1 (surround left/surround right channel) (2) Trap value in power-on reset : 1 : manufactory test mode 0 : normal operation
156	ASDATA2	Inout 4MA PD SMT	(1) Audio serial data 2 (center/left channel) (2) Trap value in power-on reset : 1 : manufactory test mode 0 : normal operation

Pin Number	Symbol	Type	Description
157	ASDATA3	Inout 4MA PD SMT	(1) Audio serial data 3 (surround left/surround right channel) (2) Trap value in power-on reset : 1 : manufactory test mode 0 : normal operation OR Videoin Data PortB 1
158	ASDATA4	Inout 4MA PD SMT	(1) Audio serial data 4 (center/left channel) (2) Trap value in power-on reset : 1 : manufactory test mode 0 : normal operation OR Videoin Data PortB 2
159	DACVDDC	Power	3.3V power pin for VIDEO DAC circuitry
160	VREF	Analog input	Bandgap reference voltage
161	FS	Analog output	Full scale adjustment
162	YUV0/CIN	Output 4MA, SR	Video data output bit 0 / Compensation capacitor
163	DACVSSC	Ground	Ground pin for VIDEO DAC circuitry
164	YUV1/C	Output 4MA, SR	Video data output bit 1 / Analog chroma output
165	DACVddb	Power	3.3V power pin for VIDEO DAC circuitry
166	YUV2/Y	Output 4MA, SR	Video data output bit 2 / Analog Y output
167	DACVSSB	Ground	Ground pin for VIDEO DAC circuitry
168	YUV3/CVBS	Output 4MA, SR	Video data output bit 3 / Analog composite output
169	DACVDDA	Power	3.3V power pin for VIDEO DAC circuitry
170	YUV4/G	Output 4MA, SR	Video data output bit 4 / Green or Y
171	DACVSSA	Ground	Ground pin for VIDEO DAC circuitry
172	YUV5/B	Output 4MA, SR	Video data output bit 5 / Blue or CB
173	YUV6/R	Output 4MA, SR	Video data output bit 6 / Red or CR
174	ICE	Input PD, SMT	Microcontroller ICE mode enable
175	BLANK#	Inout 4MA, SR SMT	Video blank area, active low / Videoin Field_601
176	VSYN	Inout 4MA, SR SMT	Vertical sync / Videoin Vsync_601
177	YUV7	Inout 4MA, SR SMT	Video data output bit 7 / Videoin Data PortB 3
178	DVSS	Ground	Ground pin for internal digital circuitry
179	HSYN	Inout 4MA, SR SMT	Horizontal sync / Videoin Hsync_601
180	SPMCLK	Input	Audio DAC master clock of SPDIF input / Videoin Data PortB 4

Pin Number	Symbol	Type	Description
181	SPDATA	Input	Audio data of SPDIF input / Videoin Data PortB 5
182	DVDD2	Power	2.5V power pin for internal digital circuitry
183	SPLRCK	Input	Audio left/right channel clock of SPDIF input / Videoin Data PortB 6
184	SPBCK	Input	Audio bit clock of SPDIF input / Videoin Data PortB 7
185	DVDD3	Power	3.3V power pin for internal digital circuitry
186	XTALO	Output	Crystal output
187	XTALI	Input	Crystal input
188	PRST	Input PD, SMT	Power on reset input, active high
189	DVSS	Ground	Ground pin for internal digital circuitry
190	VFO13	Output	The 1st, 3rd header VFO pulse output
191	IDGATE	Output	Header detect signal output
192	DVDD3	Power	3.3V power pin for internal digital circuitry
193	UDGATE	Output	DVD_RAM recording data gate signal output
194	WOBSI	Input	Wobble signal input
195	SDATA	Output	RF serial data output
196	SDEN	Output	RF serial data latch enable
197	SLCK	Output	RF serial clock output
198	BDO	Input	Flag of defect data input status
199	ADCVSS	Ground	Ground pin for ADC circuitry
200	ADIN	Analog Input	General A/D input
201	RFSUBI	Analog Input	RF subtraction signal input terminal
202	TEZISLV	Analog Input	Tracking error zero crossing low pass input
203	TEI	Analog Input	Tracking error input
204	CSO	Analog Input	Central servo input
205	FEI	Analog Input	Focus error input
206	RFLEVEL	Analog Input	Sub beam add input or RFRP low pass input
207	RFRP_DC	A Input	RF ripple detect input
208	RFRP_AC	Analog Input	RF ripple detect input (through AC coupling)
209	HRFZC	Analog Input	High frequency RF ripple zero crossing
210	PWMVREF	A Input	A reference voltage input for PWM circuitry. A typical value of 4.0 v
211	PWM2VREF	A Input	A reference voltage input for PWM circuitry. A typical value of 2.0 v
212	ADCVDD3	Power	3.3V power pin for ADC circuitry
213	RFDTSLVP	Analog Output	Positive RF data slicer level output
214	RFDTSLVN	Analog Output	Negative RF data slicer level output
215	RFIN	Analog Input	Negative input of RF differential signal
216	RFIP	Analog Input	Positive input of RF differential signal



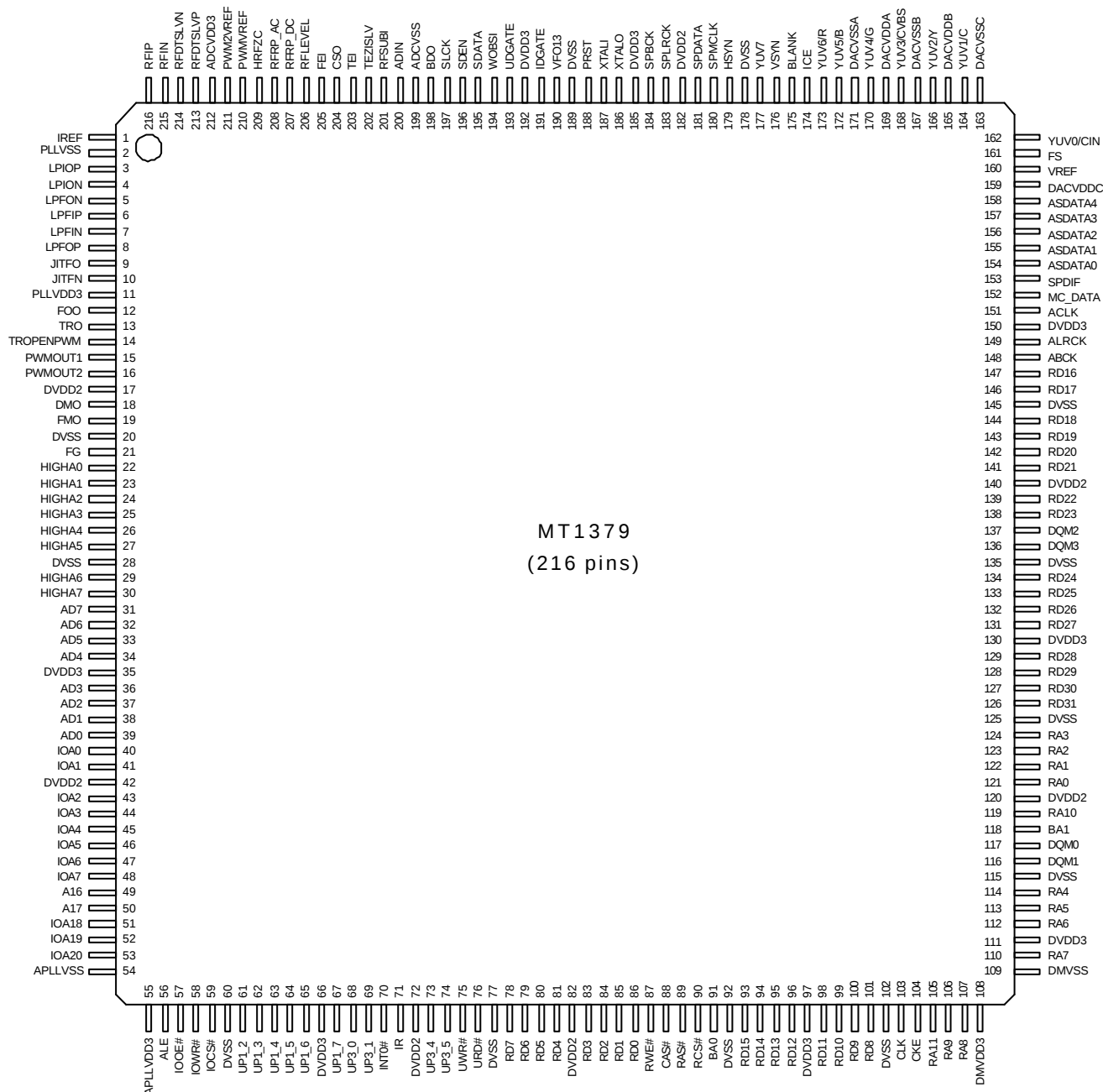
MT1379

PRELIMINARY, SUBJECT TO CHANGE WITHOUT NOTICE

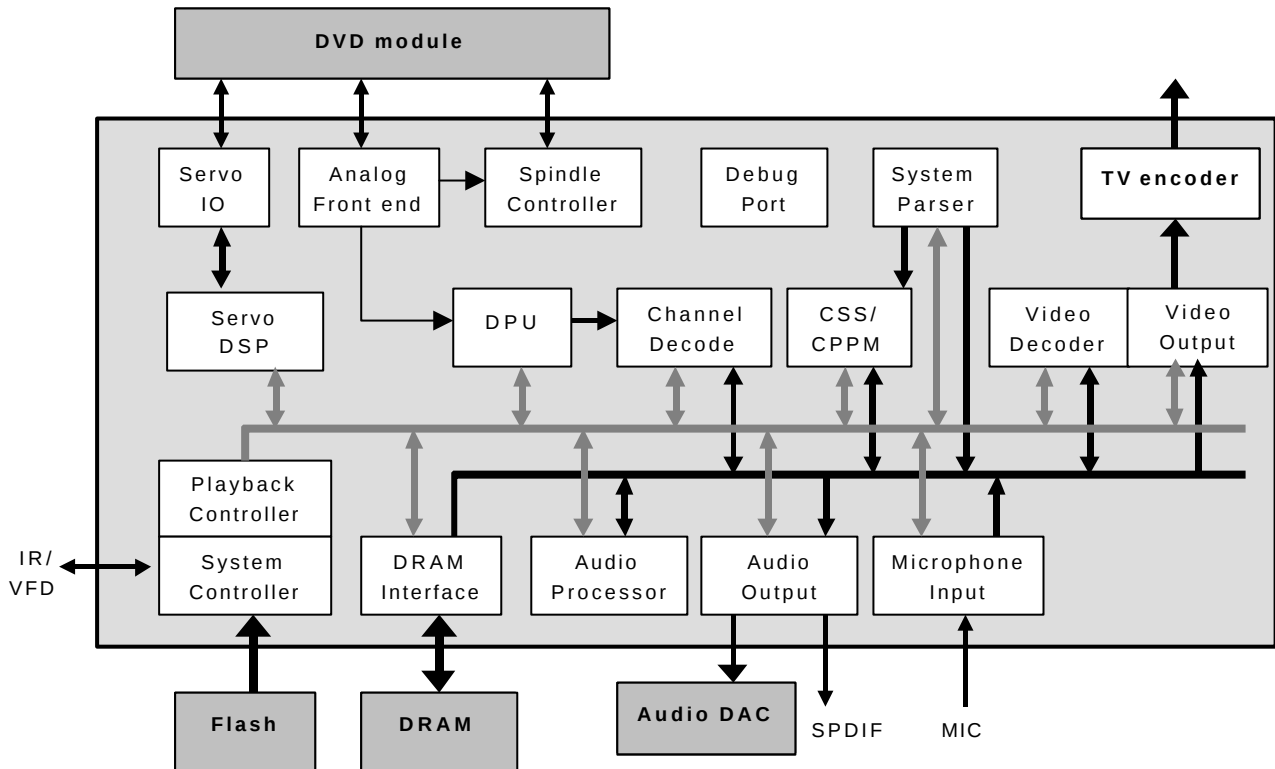
MTK CONFIDENTIAL, NO DISCLOSURE

26 Jul, 2002

Page 1 of 2



FUNCTIONAL BLOCK



Servo Controller

The servo control is accomplished through the servo DSP (Servo Digital Signal Processor) and its accessory I/O circuits. This servo DSP is capable of performing complex operations and also provides a friendly interface for the system controller. By issuing type 1 and type 2 commands from the system controller, the servo DSP can accomplish various complicated servo control functions, such as tracking, seeking and MT1336/MT1376 chip register programming. As for the servo I/O circuits, it provides interface between the input servo signals and the Servo DSP. It has built-in ADCs to digitize the servo control signal and DACs to provide signals for the actuator and sledge motor. It also has a serial interface to communicate with the MT1336/MT1376 chip.

Analog Front End

The analog front end contains a data slicer circuit and a data PLL circuit. The RF analog signal from MT1336/MT1376 is quantized by the data slicer to form the EFM/EFM+ bit stream, from which the channel bit clock is extracted by the data PLL. The EFM/EFM+bit stream and bit clock are then output to DPU for channel bit processing.

DPU

Data path unit (DPU) provides protection on data with lost synchronization patterns and demodulates EFM/EFM+ bit stream into the channel raw data that will be corrected by the decoder. The synchronization protection makes data after the synchronization pattern to be extracted even if the synchronization pattern is not found.

Spindle Controller

The spindle controller is used to control disc spindle motor. It includes a varipitch CLV clock generator, a CLV/CAV controller, and a PWM generator. The varipitch CLV clock enerator generates a reference colck for the speed of operation. The CLV/CAV

controller changes the mode and speed of operation according to servo register setting. The PWM generator generates pulse-width-modulated signal to drive disc spindle motor driver.

CSS/CPPM

The CSS/CPPM module provides functions necessary for decoding discs conforming to CSS/CPPM specification.

System Parser

The system parser is used to help the system controller to decode DVD/SVCD/VCD bitstream just after the channel decoder performing error correction. Acting as a DMA master, it moves bitstream data from RSPC buffer to video, audio, or sub-picture buffer according to system controller request. It also decrypts the scramble data of the CSS/CPPM sectors. Another function of system parser is providing system controller/DSP a DRAM memory copy controller to enhance system controller/DSP performance.

Video Decoder

The primary function of MT1379 is to support MPEG1 and MPEG2 video decoding. The video decode engine comprises of variable length decoder (VLD), inverse transformer (IT), motion compensator (MC), and block reconstructor (BR). The video decode engine decodes the variable length encoded symbols in MPEG bitstream and performs inverse scan, inverse quantization, mismatch control and inverse discrete cosine transform onto the variable length decoded data. The motion compensator fetches prediction data from reference picture buffer according to motion vectors and motion prediction mode for P and B pictures. Finally, the block reconstructor combines both the results of inverse transformer and motion compensator to derive the reconstructed image macroblock and write back to picture buffer.

The video decode engine can also support JPEG and BMP file decoding by common image compression hardware kernels.

Video Output

The Video Output unit contains Video Processor, SPU, OSD, Cursor, TV encoder units, it performs

- Reading decoded video from DRAM buffer
- Scaling the image
- Gamma/Brightness/Hue/Saturation adjustment and edge enhancement
- Reading and decoding SPU and OSD data from DRAM buffer
- Generating hardware cursor image
- Merging the video data, SPU, OSD and cursor

Video Processor

The Video Processor unit controls the transfer of video data stored in the DRAM to an internal or external TV encoder. It uses FIFOs to buffer outgoing luminance and chrominance data, and performs YUV420 to YUV422 conversion and arbitrary vertical/horizontal decimation/interpolation, from 1/4x to 256x. With this arbitrary ratio scaling capability, the Video Processor can perform arbitrary image conversion, such as PAL to NTSC, NTSC to PAL, MPEG1 to MPEG2, Letterbox, Pan-Scan conversion or zoom in, zoom out. It is also capable of interlace to progressive conversion.

The Video Processor unit performs the following functions:

- Requests and receives the decoded picture data from the picture buffer in external DRAM for display
- Resample vertical data to create 4:2:2 sample format
- Optionally performs vertical/horizontal resampling of both luminance and chrominance data
- Performs optional Gamma correction, luminance/chrominance adjustment, and edge enhancement

The Video Processor unit contains two 2-tap vertical filters for luminance and chrominance. These filters are used to interpolate and reposition luminance and chrominance line to improve picture quality. These filters are capable of generating up to eight, unique subline value between two consecutive scan lines. The generation of lines depends on the ratio between the height of the source image and the target image. In applications where DRAM bandwidth are critical the filters can be configured as simple line-repeating to reduce the DRAM bandwidth required.

The Video Processor unit integrates two separate horizontal postprocessing filter, a simple 2-tap linear horizontal filter and an 8-tap programmable filter. These filters are provided for scaling images horizontally along the scan line. These two filters is capable of generating up to eight, unique subpixel values between two consecutive pixels on a scan line. The generation of pixels depends on the ratio between the width of the source image and the target image.

SPU

This is a hardware sub-picture decoder. It decodes the compressed SPU image bitstream and CHG_COLCON commands according to SPU header information previously decoded by system controller. The SPU module also allows two SPU objects to be displayed at the same time. SPU image is blended with main video stream.

OSD

The OSD module can operate with 2/4/16/256-color bitmap format (1/2/4/8 bits), and 16/256 color RLC format, all have 16 levels of transparency. In addition, it accepts an special WARP mode, which inserts one programmable RLC code in the bitmap to reduce the image size stored in DRAM. It also features automatic shadow/outline generation in 2-color mode, 2 Highlight areas, 1 ChangeColor area and 1 OSDVoid area. One OSD area can occupy the full or a partial screen, or multiple OSDs can occur in a screen at the same time, only if they don't occupy the same horizontal line. The output image is blended with the video-SPU mixed stream.

Cursor

A hardware cursor generator is integrated in Video Output Unit. The cursor image is a 32x32 4-color bitmap image, each colors are programmable. Cursor can be enlarged by 2 in both vertical and horizontal directions. Cursor image is multiplexed with video-SPU-OSD mixed stream.

Audio Interface

Audio interface consists of Audio Output Interface and Microphone Input Interface.

Audio Output Interface

The MT1379 can support up to 8 channel audio outputs. The output formats can be 16, 24, or 32-bit frames. Left alignment, right alignment, or I²S formats are all supported.

With built-in PLL, MT1379 can provide the audio clock (ACLK) for external audio DAC at 384Fs, where Fs is usually 32KHz, 44.1KHz, 48KHz, 96KHz, or 192KHz. ACLK can also be programmed to be from outside MT1379. When ACLK is input to MT1379, the frequency could be 128*n Fs, where n is from 1 to 7.

Audio raw (encoded) data or cooked (decoded) data can be output on a single line using S/PDIF interface. The output slew rate and driving force of this pad are programmable.

Microphone Input Interface

The MT1379 provides a microphone input interface. Two independent microphones' data could be input to the MT1379. There are two independent digital volume control for these two input channels. The input data formats can also be left alignment, right alignment, or I²S formats.

System Controller

MT1379 uses an embedded Turbo-8032 as System Controller and provide ICE interface to increase the feasibility of F/W development. Also, MT1379 includes an build-in internal 373 to latch lower byte address from 8032 Port 0 and provide a glue-logic free solution. MT1379 supports up to 1M X 16 bits Flash ROM to store 8032 code, H/W related data, User data, etc. F/W upgrade can be achieved either by debug interface or by disk.

ELECTRICAL CHARACTERISTICS

Absolute Maximum Rating

Symbol	Parameters	Value	Unit
VDD3	3.3V Supply voltage	-0.3 to 3.6	V
VDD2	2.5V Supply voltage	-0.3 to 3.0	V
VDDA	Analog Supply voltage	-0.3 to 3.6	V
V _{IN}	Input Voltage	-0.3 to 5.5	V
V _{OUT}	Output Voltage	-0.3 to VDD3+0.3	V
Ta	Ambient Temperature	0 to 70	°C

DC Characteristics

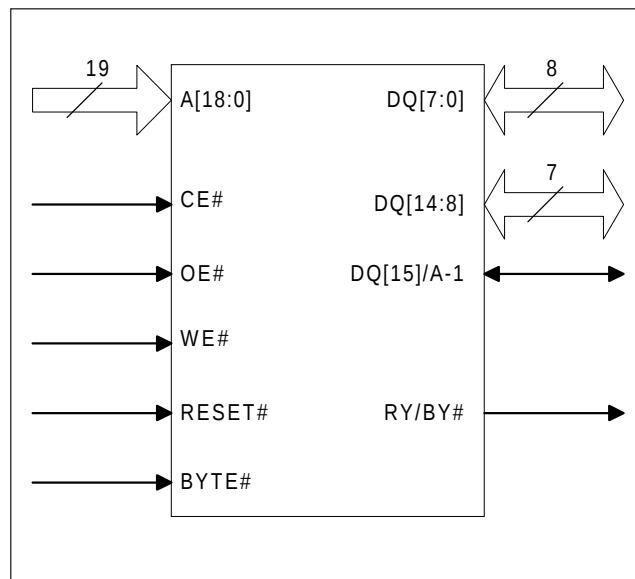
Symbol	Parameters	Min	Typ	Max	Unit
V _{IH}	Input voltage high	2.4	-	3.6	V
V _{IL}	Input voltage low	-	-	0.8	V
V _{OH}	Output voltage high	3.0	-	VDD3	V
V _{OL}	Output voltage low	-	-	0.5	V
I _{IH}	High level input current			10	uA
I _{IL}	Low level input current	-10			uA
P _D	Power dissipation		1.0		W
P _{Down}	Power down mode			0.1	W

IC BLOCK DIAGRAM & DESCRIPTION

8.3 U214 HY29F800

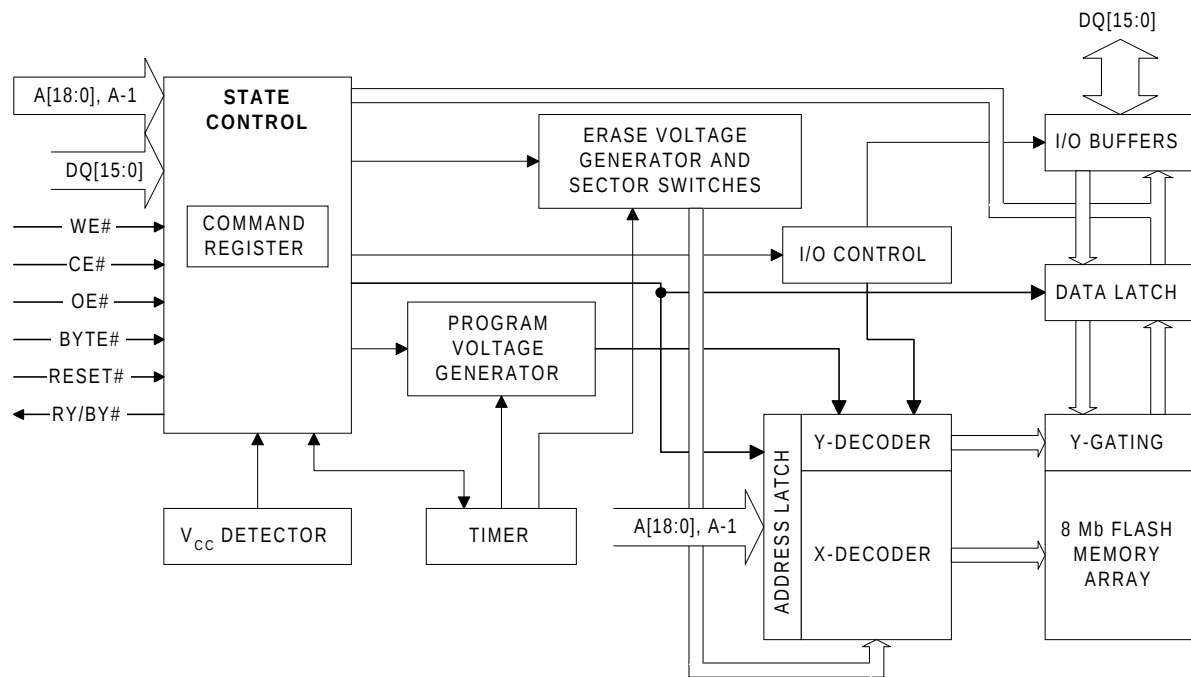
KEY FEATURES

- **5 Volt Read, Program, and Erase**
 - Minimizes system-level power requirements
- **High Performance**
 - Access times as fast as 55 ns
- **Low Power Consumption**
 - 20 mA typical active read current in byte mode, 28 mA typical in word mode
 - 35 mA typical program/erase current
 - 5 μ A maximum CMOS standby current
- **Compatible with JEDEC Standards**
 - Package, pinout and command-set compatible with the single-supply Flash device standard
 - Provides superior inadvertent write protection
- **Sector Erase Architecture**
 - Boot sector architecture with top and bottom boot block options available
 - One 16 Kbyte, two 8 Kbyte, one 32 Kbyte and fifteen 64 Kbyte sectors in byte mode
 - One 8 Kword, two 4 Kword, one 16 Kword and fifteen 32 Kword sectors in word mode
 - A command can erase any combination of sectors
 - Supports full chip erase
- **Erase Suspend/Resume**
 - Temporarily suspends a sector erase operation to allow data to be read from, or programmed into, any sector not being erased
- **Sector Protection**
 - Any combination of sectors may be locked to prevent program or erase operations within those sectors
- **Temporary Sector Unprotect**
 - Allows changes in locked sectors (requires high voltage on RESET# pin)
- **Internal Erase Algorithm**
 - Automatically erases a sector, any combination of sectors, or the entire chip
- **Internal Programming Algorithm**
 - Automatically programs and verifies data at a specified address
- **Fast Program and Erase Times**
 - Byte programming time: 7 μ s typical
 - Sector erase time: 1.0 sec typical
 - Chip erase time: 19 sec typical
- **Data# Polling and Toggle Status Bits**
 - Provide software confirmation of completion of program or erase operations
- **Ready/Busy# Output (RY/BY#)**
 - Provides hardware confirmation of completion of program and erase operations
- **Minimum 100,000 Program/Erase Cycles**
- **Space Efficient Packaging**
 - Available in industry-standard 44-pin PSOP and 48-pin TSOP and reverse TSOP packages



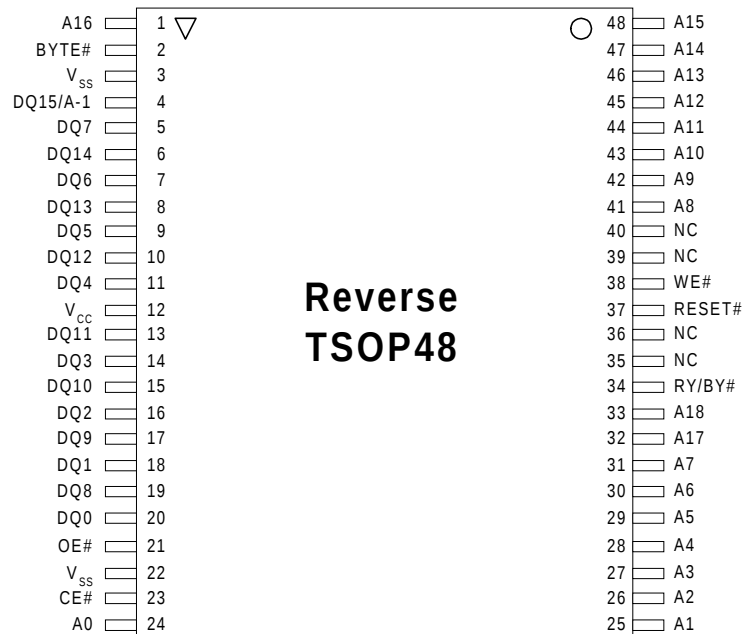
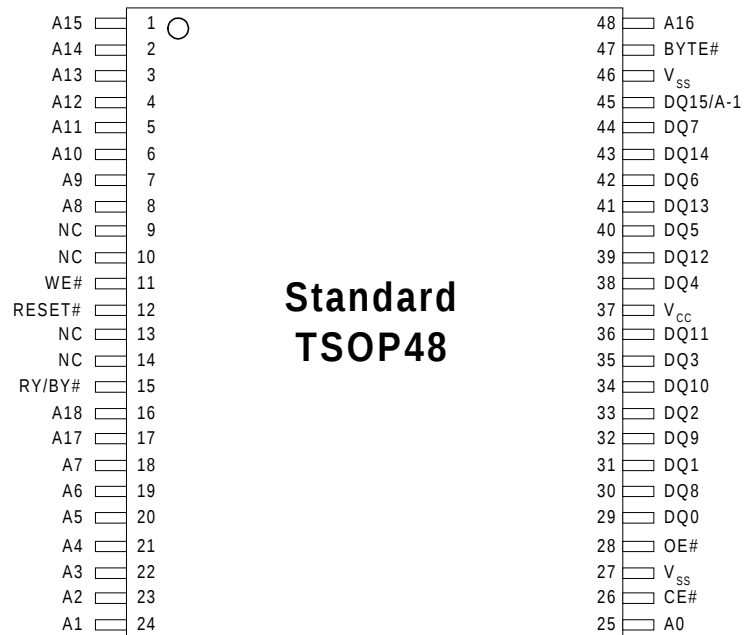
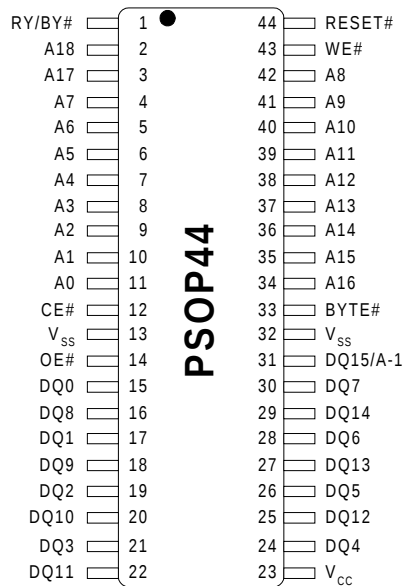
IC BLOCK DIAGRAM & DESCRIPTION

BLOCK DIAGRAM



IC BLOCK DIAGRAM & DESCRIPTION

PIN CONFIGURATIONS



IC BLOCK DIAGRAM & DESCRIPTION

8.4 U203 SDRAM-HY57V1610D

2 Banks x 512k x 16 Bit Synchronous DRAM

DESCRIPTION

THE Hynix HY57V161610D is a 16,777,216-bits CMOS Synchronous DRAM, ideally suited for the Mobile applications which require low power consumption and industrial temperature range. HY57V161610D is organized as 2banks of 524,288x16.

HY57V161610D is offering fully synchronous operation referenced to a positive edge clock. All inputs and outputs are synchronized with the rising edge of the clock input. The data paths are internally pipelined to achieve very high bandwidth. All input and output voltage levels are compatible with LVTTL.

Programmable options include the length of pipeline (Read latency of 1,2 or 3), the number of consecutive read or write cycles initiated by a single control command (Burst length of 1,2,4,8 or full page), and the burst count sequence(sequential or interleave). A burst of read or write cycles in progress can be terminated by a burst terminate command or can be interrupted and replaced by a new burst read or write command on any cycle. (This pipeline design is not restricted by a `2N` rule.)

FEATURES

- Single 3.0V to 3.6V power supply ^{Note1)}
- All device pins are compatible with LVTTL interface
- JEDEC standard 400mil 50pin TSOP-II with 0.8mm of pin pitch
- All inputs and outputs referenced to positive edge of system clock
- Data mask function by UDQM/LDQM
- Internal two banks operation
- Auto refresh and self refresh
- 4096 refresh cycles / 64ms
- Programmable Burst Length and Burst Type
 - 1, 2, 4, 8 and Full Page for Sequence Burst
 - 1, 2, 4 and 8 for Interleave Burst
- Programmable CAS Latency ; 1, 2, 3 Clocks

ORDERING INFORMATION

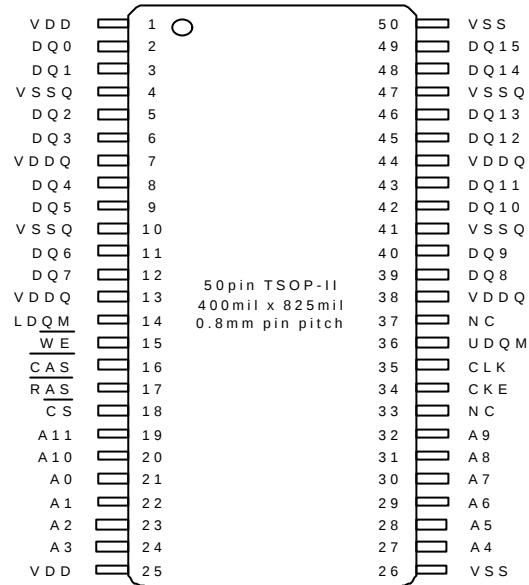
Part No.	Clock Frequency	Organization	Interface	Package
HY57V161610DTC-55I	183MHz	2Banks x 512Kbits x 16	LVTTL	400mil 50pin TSOP II
HY57V161610DTC-6I	166MHz			
HY57V161610DTC-7I	143MHz			
HY57V161610DTC-10I	100MHz			

This document is a general product description and is subject to change without notice. Hyundai Electronics does not assume any responsibility for use of circuits described. No patent licenses are implied

Rev. 0.2/Aug.01

IC BLOCK DIAGRAM & DESCRIPTION

PIN CONFIGURATION



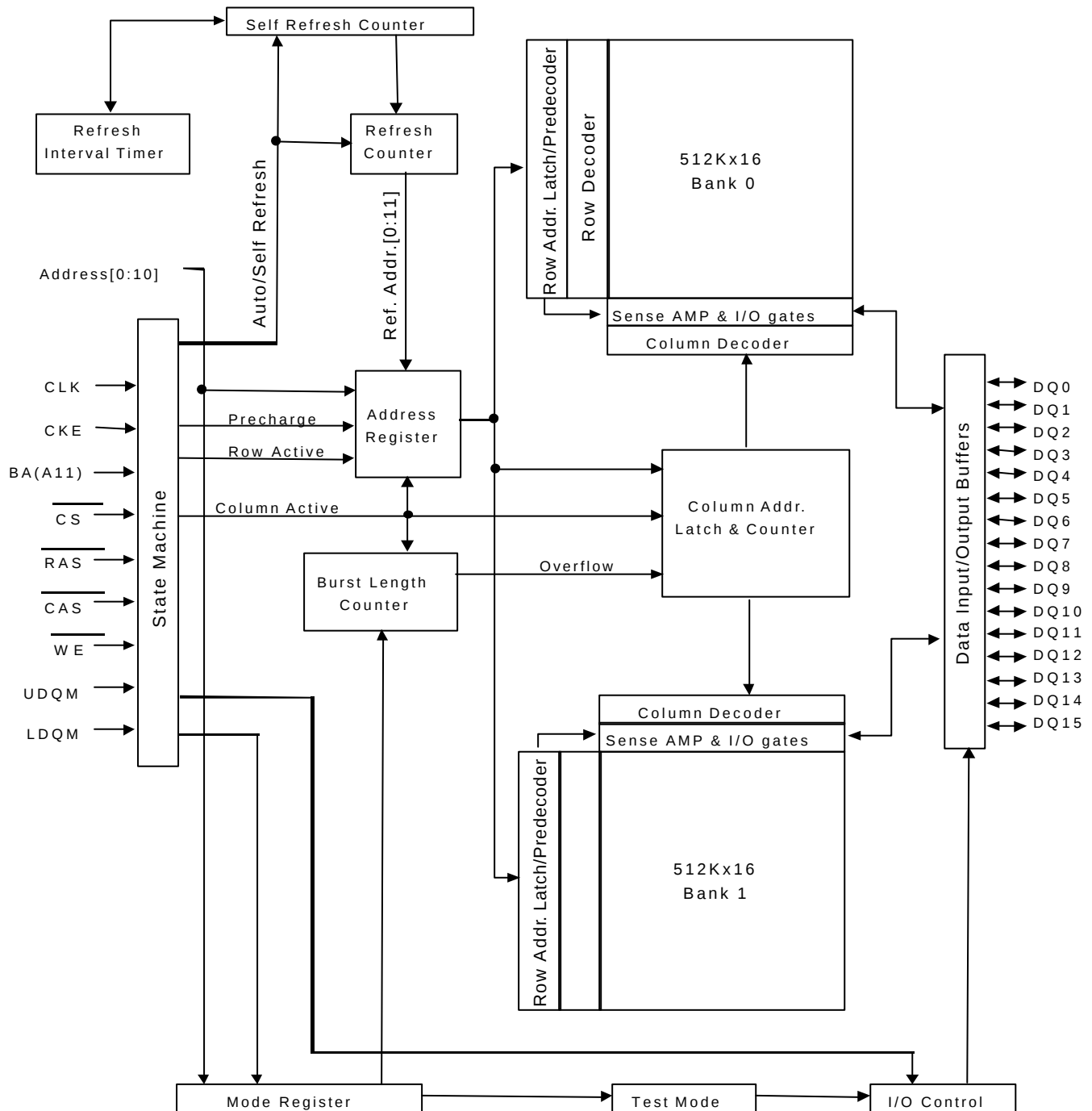
PIN DESCRIPTION

PIN	PIN NAME	DESCRIPTION
CLK	Clock	The system clock input. All other inputs are referenced to the SDRAM on the rising edge of CLK.
CKE	Clock Enable	Controls internal clock signal and when deactivated, the SDRAM will be one of the states among power down, suspend or self refresh.
$\overline{\text{CS}}$	Chip Select	Command input enable or mask except CLK, CKE and DQM
BA	Bank Address	Select either one of banks during both $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ activity.
A0 ~ A10	Address	Row Address : RA0 ~ RA10, Column Address : CA0 ~ CA7 Auto-precharge flag : A10
$\overline{\text{RAS}}$, $\overline{\text{CAS}}$, $\overline{\text{WE}}$	Row Address Strobe, Column Address Strobe, Write Enable	$\overline{\text{RAS}}$, $\overline{\text{CAS}}$ and $\overline{\text{WE}}$ define the operation. Refer function truth table for details
LDQM, UDQM	Data Input/Output Mask	DQM control output buffer in read mode and mask input data in write mode
DQ0 ~ DQ15	Data Input/Output	Multiplexed data input / output pin
VDD/VSS	Power Supply/Ground	Power supply for internal circuit and input buffer
VDDQ/VSSQ	Data Output Power/Ground	Power supply for DQ
NC	No Connection	No connection

IC BLOCK DIAGRAM & DESCRIPTION

FUNCTIONAL BLOCK DIAGRAM

1Mx16 Synchronous DRAM



IC BLOCK DIAGRAM & DESCRIPTION

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Unit
Ambient Temperature	TA	- 40 ~ 85	°C
Storage Temperature	TSTG	-55 ~ 125	°C
Voltage on Any Pin relative to VSS	VIN, VOUT	-1.0 ~ 4.6	V
Voltage on VDD relative to VSS	VDD	-1.0 ~ 4.6	V
Short Circuit Output Current	IOS	50	mA
Power Dissipation	PD	1	W
Soldering Temperature·Time	TSOLDER	260·10	°C ·Sec

Note : Operation at above absolute maximum rating can adversely affect device reliability.

DC OPERATING CONDITION (TA= -40°C to 85°C)

Parameter	Symbol	Min	Typ.	Max	Unit	Note
Power Supply Voltage	VDD, VDDQ	3.0	3.3	3.6	V	1, 2
Input high voltage	VIH	2.0	3.0	VDD + 0.3	V	1, 4
Input low voltage	VIL	-0.5	0	0.8	V	1, 5

Note :

- 1.All voltages are referenced to VSS = 0V.
- 2.VDD(min) is 3.15V when HY57V161610DTC-7I operates at $\overline{\text{CAS}}$ latency=2
- 3.VIH(max) is acceptable 4.6V AC pulse width with $\leq 10\text{ns}$ of duration.
- 4.VIL(min) is acceptable -1.5V AC pulse width with $\leq 10\text{ns}$ of duration.

AC OPERATING CONDITION (TA= - 40°C to 85°C, VDD=3.0V to 3.6V, VSS=0V)

Parameter	Symbol	Value	Unit	Note
AC input high / low level voltage	VIH / VIL	2.4/0.4	V	
Input timing measurement reference level voltage	Vtrip	1.4	V	
Input rise / fall time	tR / tF	1	ns	
Output timing measurement reference level	Voutref	1.4	V	
Output load capacitance for access time measurement	CL	30	pF	1

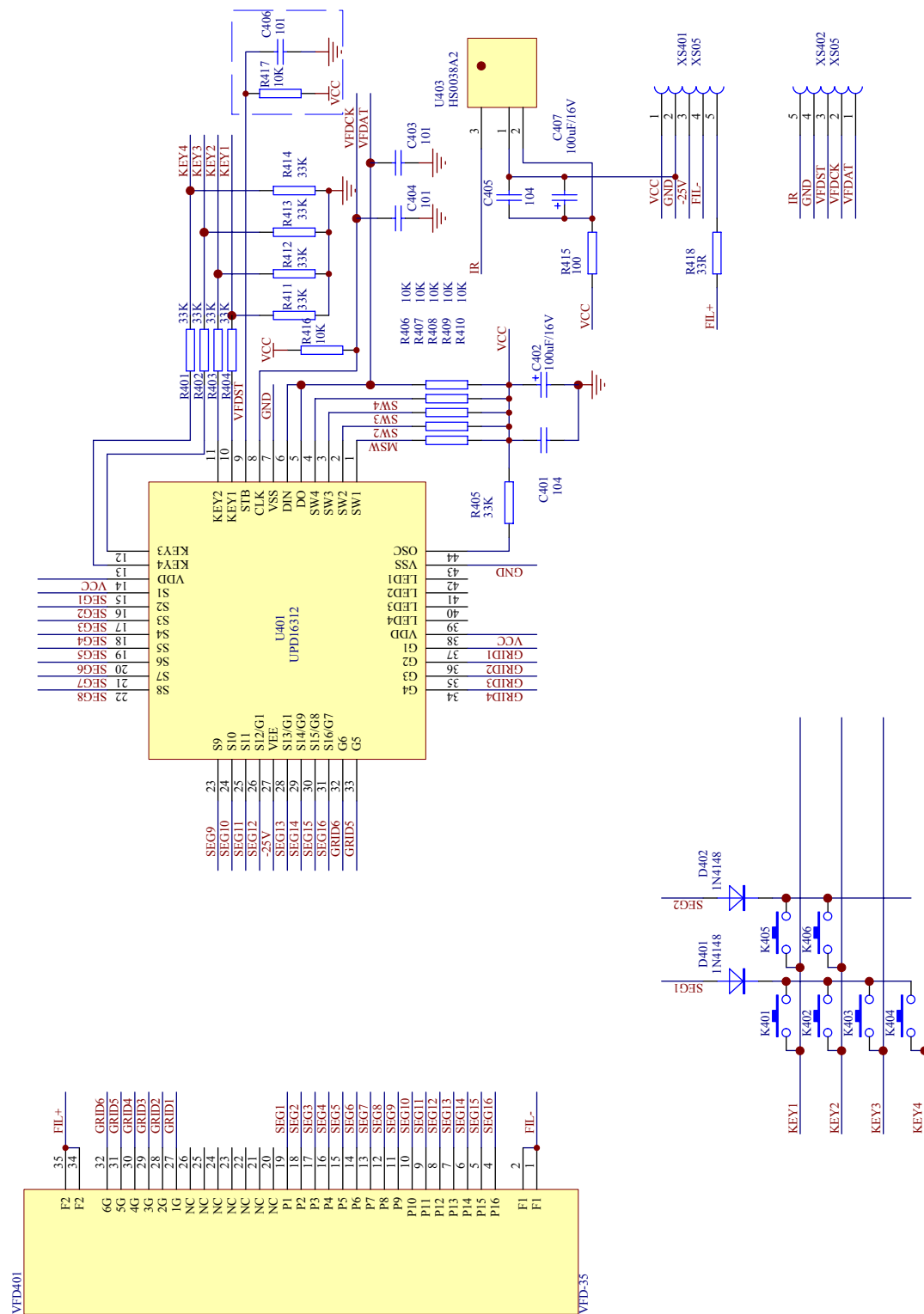
Note :

1. Output load to measure access times is equivalent to two TTL gates and one capacitance(30pF).
For details, refer to AC/DC output load circuit.
2. VDD(min) is 3.15V when HY57V161610DTC-7I operates at $\overline{\text{CAS}}$ latency=2 and tCK2=8.9ns

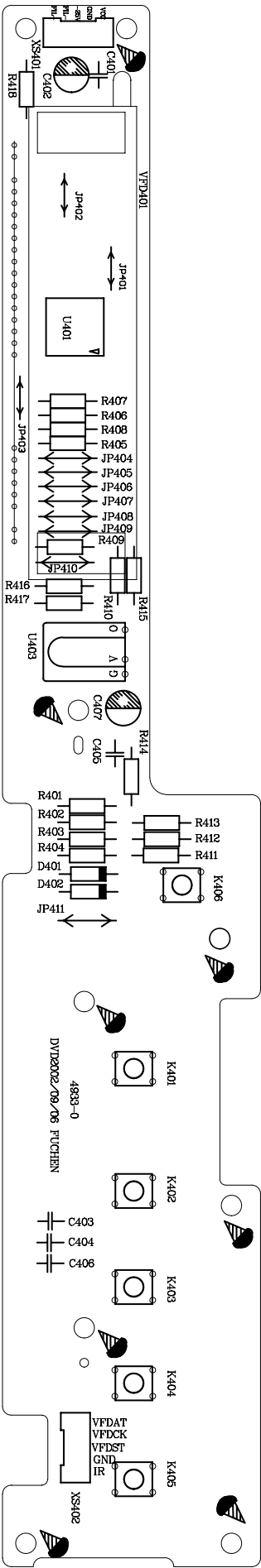
IC BLOCK DIAGRAM & DESCRIPTION

9. SCHEMATIC & PCB WIRING DIAGRAM

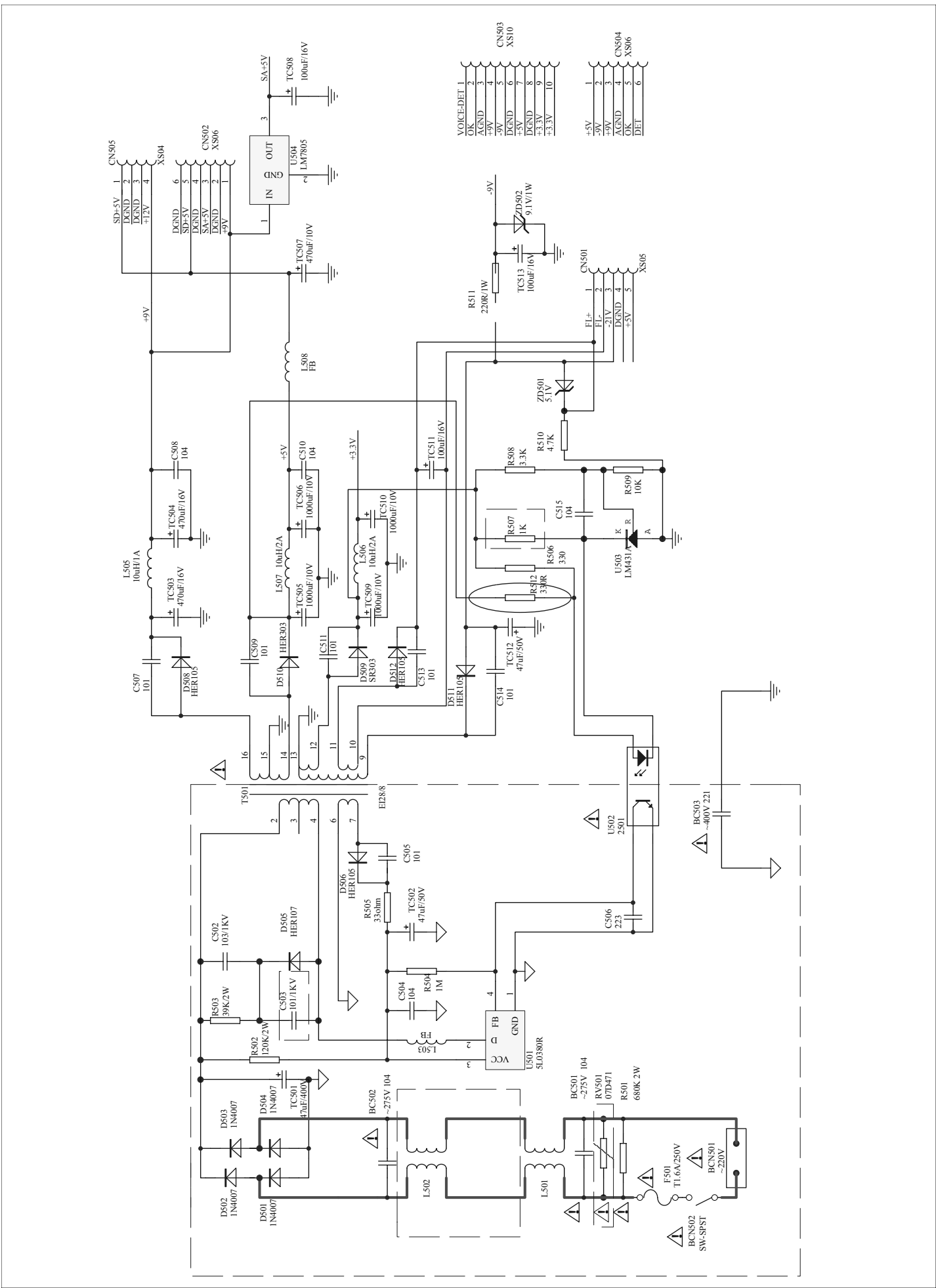
FRONT SCHEMATIC DIAGRAM



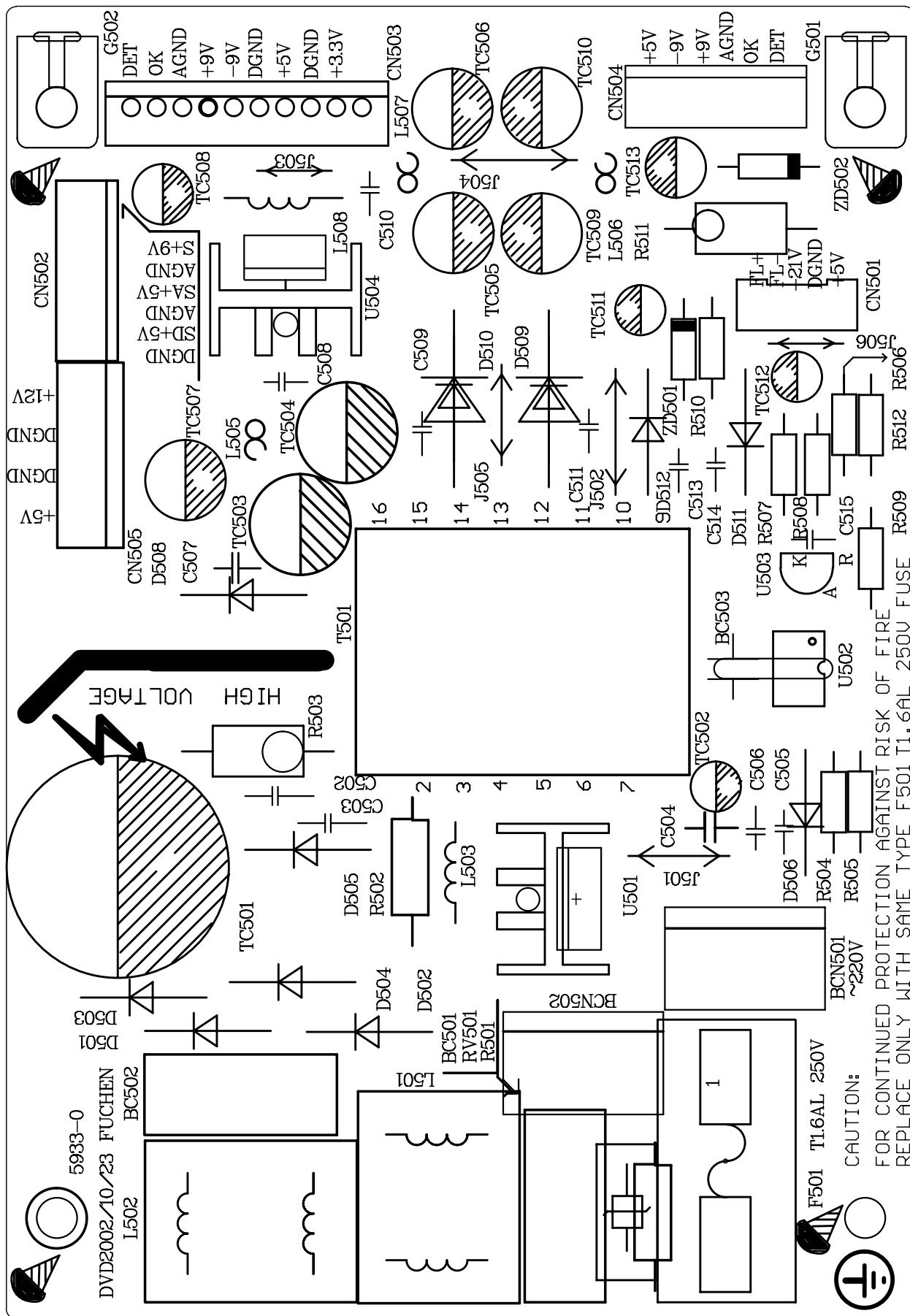
FRONT SCHEMATIC DIAGRAM



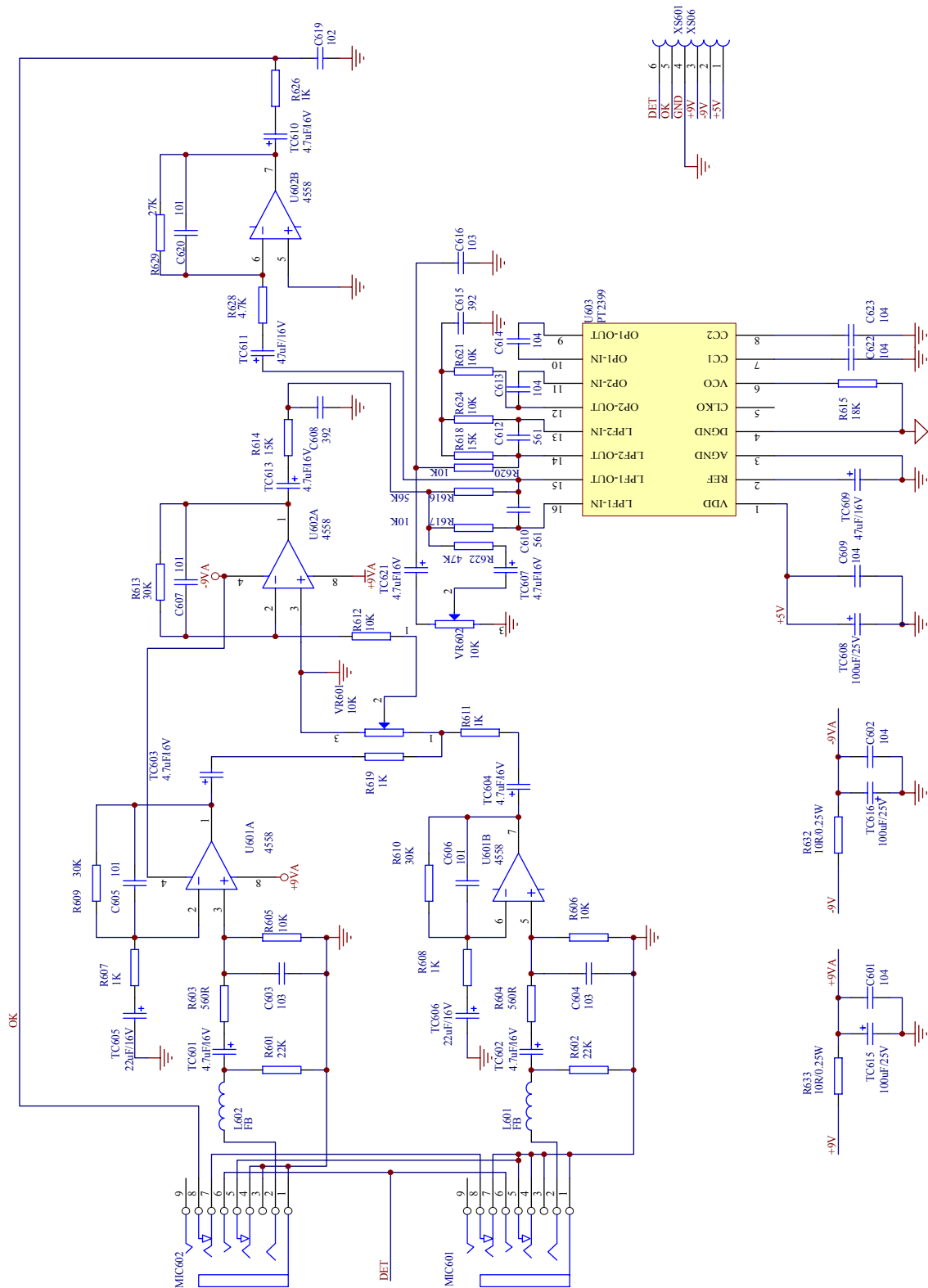
POWER BOARD SCHEMATIC DIAGRAM



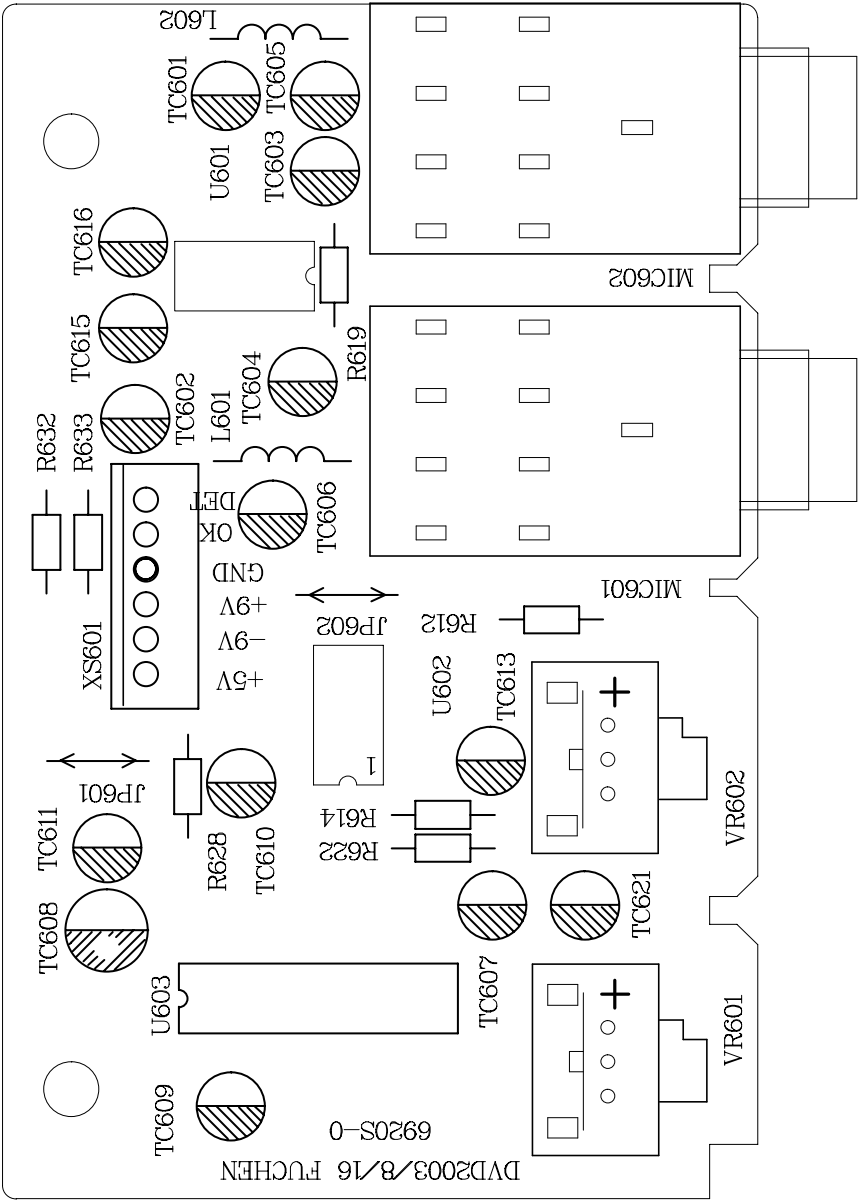
POWER BOARD SCHEMATIC DIAGRAM



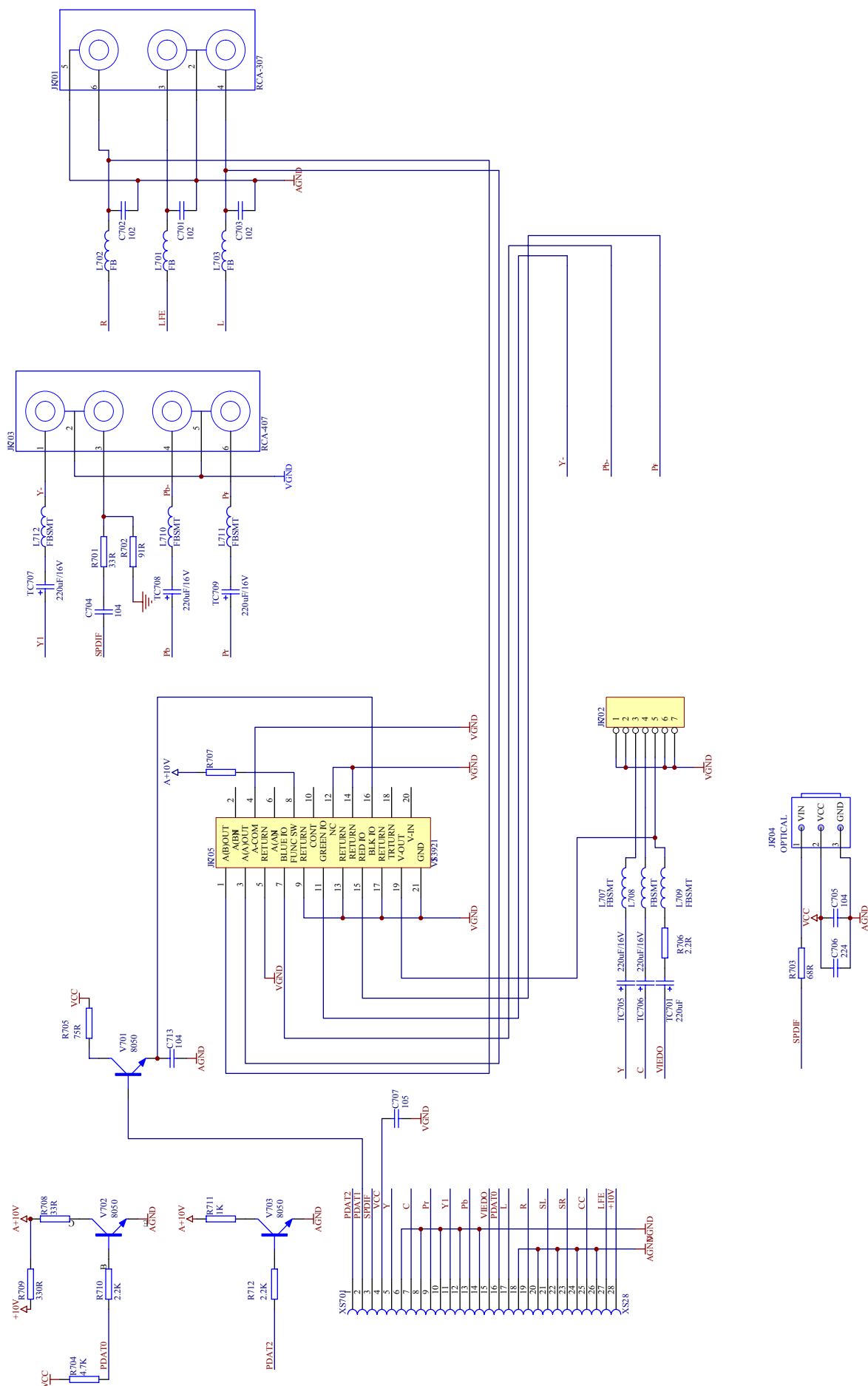
OK SCHEMATIC DIAGRAM



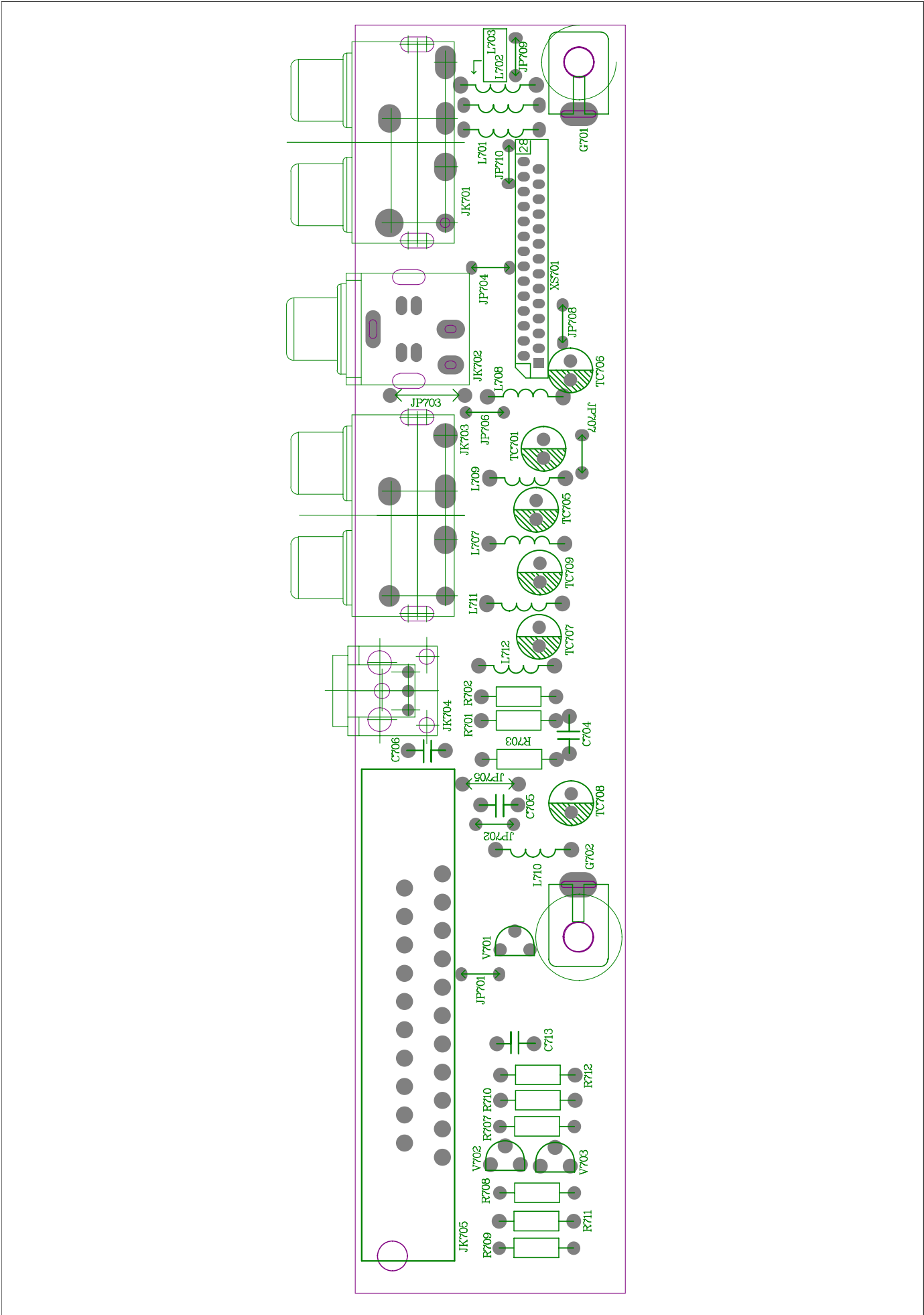
OK SCHEMATIC DIAGRAM



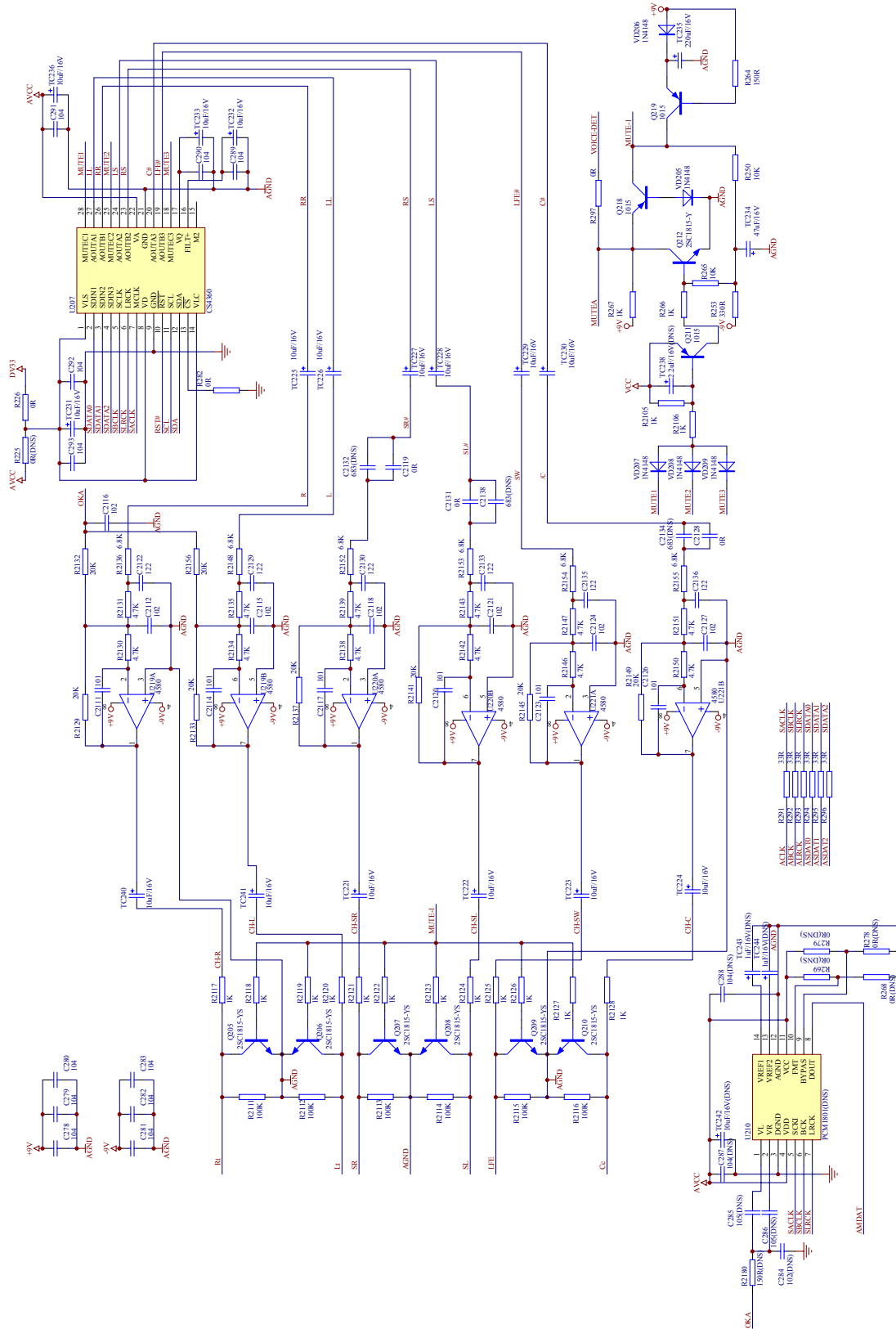
OUTPUT BOARD SCHEMATIC DIAGRAM



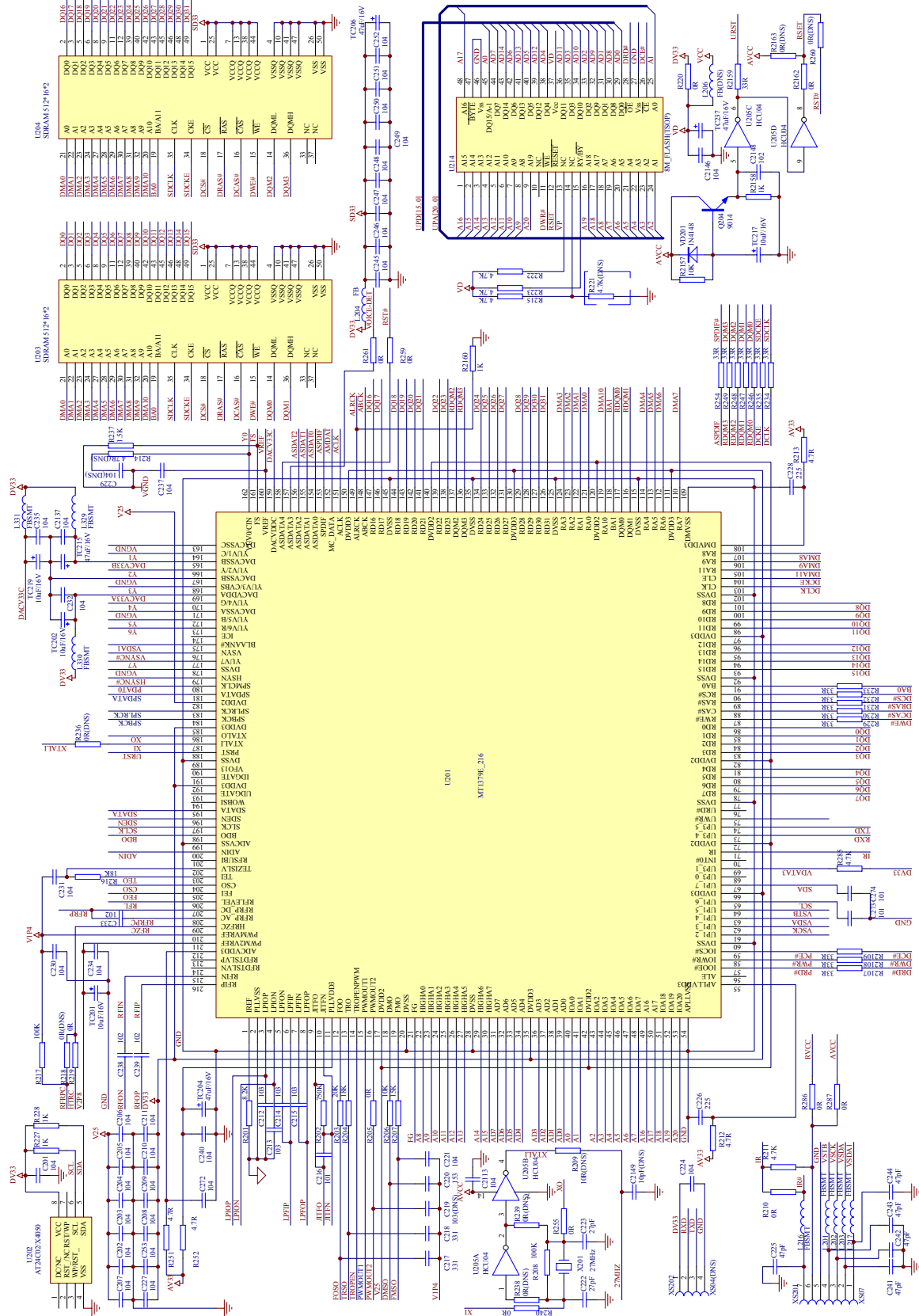
OUTPUT BOARD SCHEMATIC DIAGRAM



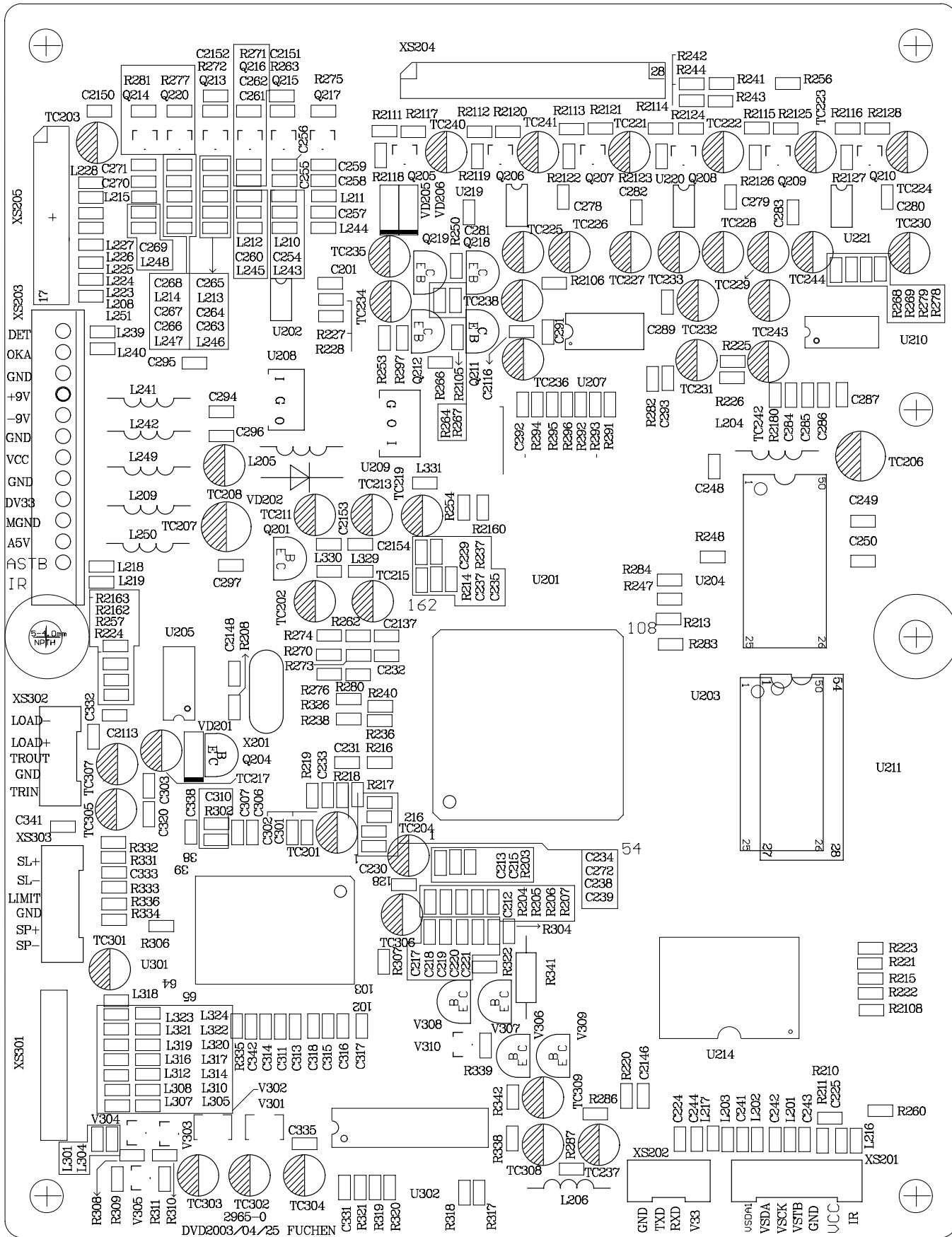
MIAN SCHEMATIC DIAGRAM



MIAN SCHEMATIC DIAGRAM



MIAN SCHEMATIC DIAGRAM



10. SPARE PARTS LIST

BBK20S (RU) MATERIAL LIST

1. DECODE BOARD

NO		MATERIAL	SPECIFICATIONS/PART NUMBER	QUANTITY	LOCATION
1		SMD RESISTOR	1/16W 0 Ω $\pm$ 5%	22	L243~L248,R205,R219,R220,R226,R240,R241,R243,R255,R257,R259,R282,R332,R337,R2162,R286,R297
2		SMD RESISTOR	1/16W 75 Ω $\pm$ 5%	1	R256
3		CARBON FILM RESISTOR	1/4W2.2 Ω $\pm$ 5%	1	R341
4		SMD RESISTOR	1/16W1 Ω $\pm$ 5%	5	R312,R313,R317,R318,R336
5		SMD RESISTOR	1/16W 4.7 Ω $\pm$ 5%	4	R212,R213,R251,R252
6		SMD RESISTOR	1/16W 15 Ω $\pm$ 5%	2	R314,R315
7		SMD RESISTOR	1/16W 33 Ω $\pm$ 5%	21	R2107~R2109,R2159,R229~R235,R246,R247,R254,R248,R249,R291~R294,R296
8		SMD RESISTOR	1/16W 470 Ω $\pm$ 5%	2	R322,R323
9		SMD RESISTOR	1/16W 150 Ω $\pm$ 5%	13	R262~R264,R270~R277,R280,R281
10		SMD RESISTOR	1/16W 330 Ω $\pm$ 5%	1	R253
11		SMD RESISTOR	1/16W 1K $\pm$ 5%	14	R227,R228,R266,R267,R2105,R2106,R2117~R2120,R2125,R2126,R2158,R2160
12		SMD RESISTOR	1/16W 1.5K $\pm$ 5%	2	R338,R342
13		SMD RESISTOR	1/16W 2K $\pm$ 5%	1	R237
13		SMD RESISTOR	1/16W 4.7K $\pm$ 5%	9	R222,R223,R2130,R2131,R2134,R2135,R2146,R2147,R285
14		SMD RESISTOR	1/16W 6.8K $\pm$ 5%	3	R2136,R2148,R2154
15		SMD RESISTOR	1/16W 8.2K $\pm$ 5%	1	R201
16		SMD RESISTOR	1/16W 10K $\pm$ 5%	13	R206,R250,R265,R303~R306,R309,R311,R319,R339,R2157,R210
17		SMD RESISTOR	1/16W 15K $\pm$ 5%	2	R207,R307
18		SMD RESISTOR	1/16W 20K $\pm$ 5%	4	R203,R316,R320,R321
19		SMD RESISTOR	1/16W 18K $\pm$ 5%	2	R204,R216
20		SMD RESISTOR	1/16W24K $\pm$ 5%	5	R2129,R2133,R2145,R2132,R2156
21		PRECISION SMD RESISTOR	1/16W 330K $\pm$ 1%	2	R333,R334
22		PRECISION SMD RESISTOR	1/16W 750K $\pm$ 1%	3	R202,R331,R335
23		CD	CD11 16V22U $\pm$ 20%5 $\times$ 11 2	1	TC217
24		SMD RESISTOR	1/16W 100K $\pm$ 5%	7	R208,R2111,R2112,R2115,R217,R308,R310
25		CD	CD11 16V10U $\pm$ 20%5 $\times$ 11 2	16	TC201,TC202,TC203,TC219,TC223,TC225,TC226,TC229,TC231~TC233,TC236,TC240, TC241,TC306,TC307
26		CD	CD11 16V220U $\pm$ 20%6 $\times$ 12 2.5	6	TC207,TC208,TC211,TC213,TC235,TC301
27		CD	CD11 16V47U $\pm$ 20%5 $\times$ 11 2	11	TC204,TC206,TC215,TC234,TC237,TC302~TC305,TC308,TC309

28		SMD CAPACITOR	50V 27P ±5% NPO 0603	3	C222,C223,C333
29		SMD CAPACITOR	50V 47P ±5% NPO 0603	14	C225,C241~C243,C254,C256,C257,C259,C260,C262,C266,C268,C269,C271
30		SMD CAPACITOR	50V 82P ±5% NPO 0603	1	C305
31		SMD CAPACITOR	50V 101 ±5% NPO 0603	7	C216,C273,C274,C342,C2111,C2114,C2123
32		SMD CAPACITOR	50V 331 ±5% NPO 0603	2	C217,C218
33		SMD CAPACITOR	50V 151 ±5% NPO 0603	2	C331,C334
34		SMD CAPACITOR	50V 391 ±10% 0603	1	C304
35		SMD CAPACITOR	50V 104 +80%-20% 0603	77	C201~C211,C221,C224,C227,C230~C232,C234~C235,C237,C240,C245~C253,C272,C278~C283,C289~C297,C301~C303,C312,C313,C320~C330,C332,C335~C339,C341,C2113,C2137,C2146,C2150~C2154
	35.1	SMD CAPACITOR	25V 104 +80%-20% 0603	77	C201~C211,C221,C224,C227,C230~C232,C234~C235,C237,C240,C245~C253,C272,C278~C283,C289~C297,C301~C303,C312,C313,C320~C330,C332,C335~C339,C341,C2113,C2137,C2146,C2150~C2154
36		SMD CAPACITOR	16V 105 +80%-20% 0603	4	C315~C318
37		SMD CAPACITOR	10V 225 +80%-20% 0805	2	C226,C228
38		SMD CAPACITOR	50V 471 ±5% NPO 0603	1	C311
39		SMD CAPACITOR	50V 102 ±10% 0603	7	C233,C238,C239,C2112,C2115,C2124,C2148
40		SMD CAPACITOR	50V 122 ±10% 0603	3	C2122,C2129,C2135
41		SMD CAPACITOR	50V 103 ±10% 0603	4	C212~C215
42		SMD CAPACITOR	50V 153 ±10% 0603	3	C220,C308,C319
43		SMD CAPACITOR	16V 333 ±10% 0603	1	C306
44		SMD INDUCTOR	10UH ±10% 2012	2	L303,L306
45		SMD INDUCTOR	1.8UH ±10% 1608	6	L210~L215
46		MAGNETIC BEADS INDUCTOR	RH354708	7	L204,L205,L209,L241,L242,L249,L250
47		SMD MAGNETIC BEADS	FCM1608K-221T05	30	L201~L203,L216,L239,L240,L301,L304,L305,L307,L308,L310,L311,L312,L314,L316~L324,L329~L331,L325~L327
48		SMD DIODE	1N4148	6	VD201,VD205~VD209
	48.1	SMD DIODE	LS4148	6	VD201,VD205~VD209
	48.2	SMD DIODE	LL4148	6	VD201,VD205~VD209
49		TRIODE	C8050	3	V307,V308,Q201
50		TRIODE	8550C	2	V306,V309
51		TRIODE	9014C	1	Q204
52		TRIODE	C1815Y	1	Q212
53		SMD TRIODE	C1815	3	Q205,Q206,Q209

54		TRIODE	2SA1015	3	Q211,Q218,Q219
55		SMD TRIODE	3906	6	Q213~Q217,Q220
56		SMD TRIODE	3904	1	V305
57		SMD TRIODE	9014C	1	V310
58		SMD TRIODE	2SK3018	2	V303,V304
59		SMD TRIODE	2SB1132	2	V301,V302
60		IC	NJM4558M SOP	2	U219,U221
	60.1	IC	4580 SOP	2	U219,U221
	60.2	IC	4558 SOP	2	U219,U221
61		IC	MM74HCU04M SOP	1	U205
	61.1	IC	HCU04 SOP	1	U205
62		IC	HY57V161610DTC-7 TSOP	2	U203,U204
	62.1	IC	M12L16161A-7T SOP	2	U203,U204
	62.2	IC	AE45C16016T-7 SOP	2	U203,U204
	62.3	IC	GM72V161621ET75 SOP	2	U203,U204
63		IC	CS4360 SSOP	1	U207
64		IC	24C02N SOP	1	U202
65		IC	MT1336E-C QFP	1	U301
66		IC	MT1379EE-C QFP	1	U201
67		IC	BA5954FP HSOP	1	U302
68		CRYSTAL OSCILLATOR	27.00MHz 49-S	1	X201
69		CABLE SOCKET	14P 1.0mm STRAIGHT DUAL LINE PLUG	1	XS204
70		PCB	2965-0	1	
71		SOCKET	5P 2.0mm	1	XS302
72		SOCKET	6P 2.0mm	2	XS303,XS201
73		SOCKET	11P 2.5mm	1	XS203
74		CABLE SOCKET	24P 0.5mm SMD WITH CLASP	1	XS301

2. POWER BOARD

NO		MATERIAL	SPECIFICATIONS/PART NUMBER	QUANTITY	LOCATION
1		CARBON FILM RESISTOR	1/4W33 Ω $\pm$ 5% SHAPED 10	1	R505
2		CARBON FILM RESISTOR	1/4W330 Ω $\pm$ 5% SHAPED 10	1	R506
3		CARBON FILM RESISTOR	1/4W10K $\pm$ 5% SHAPED 10	1	R507
4		CARBON FILM RESISTOR	1/4W4.7K $\pm$ 5% SHAPED 10	1	R510
5		CARBON FILM RESISTOR	1/4W1M Ω $\pm$ 5% SHAPED 10	1	R504
6		METAL FILM RESISTOR	1/4W4.7K $\pm$ 1%	1	R508
7		METAL FILM RESISTOR	1/4W12K $\pm$ 1% SHAPED 10	1	R509
8		METAL OXIDE FILM RESISTOR	1W330 Ω $\pm$ 5% SHAPED R 15 $\times$ 8	1	R511
9		METAL OXIDE FILM RESISTOR	2W39K $\pm$ 5% SHAPED FLAT 15 $\times$ 9	1	R503
	9.1	METAL OXIDE FILM RESISTOR	2W39K $\pm$ 5% SHAPED FLAT 15 $\times$ 7	1	R503
10		METAL OXIDE FILM RESISTOR	2W120K $\pm$ 5% SHAPED FLAT 15 $\times$ 7	1	R502
11		HIGH VOLTAGE RESISTOR	1/2W680K $\pm$ 5%	1	R501

12		PORCELAIN CAPACITOR	50V 100P ±10% 5mm	6	C505,C507,C509,C511,C513,C514
13		PORCELAIN CAPACITOR	50V 104 ±20% 5mm	4	C504,C508,C510,C515
14		PORCELAIN CAPACITOR	1000V 101 +80%-20% 7.5mm	1	C503
	14.1	PORCELAIN CAPACITOR	1000V 101 ±10% 7.5mm	1	C503
15		PORCELAIN CAPACITOR	1000V 103 +80%-20% 7.5mm	1	C502
16		CERAMIC CAPACITOR	CT81 400V 221±20% 10mm	1	BC503
	16.1	CERAMIC CAPACITOR	CT81 400V221±10% 10mm	1	BC503
17		TERYLENE CAPACITOR	100V 223 ±10% 5mm	1	C506
18		TERYLENE CAPACITOR	275V 104 ±20% 15mm	1	BC501
	18.1	TERYLENE CAPACITOR	275V 104 ±10% 15mm	1	BC501
19		CD	GZ16V100U±20%6×12 2.5	3	TC508,TC511,TC513
	19.1	CD	CD11 16V100U±20%6×12 2.5	3	TC508,TC511,TC513
	19.2	CD	CD110 16V100U±20%6×12 2.5	3	TC508,TC511,TC513
	19.3	CD	CD11C 16V100U+20%-15%6×7 2.5	3	TC508,TC511,TC513
	19.4	CD	CD11C 16V100U±20%6×7 2.5	3	TC508,TC511,TC513
20		CD	CD11 25V470U+20%-10%10×16 5	2	TC503,TC504
	20.1	CD	CD11 25V470U±20%10×16 5	2	TC503,TC504
21		CD	CD11 50V47U±20%6×12 2.5	2	TC502,TC512
22		CD	CD11 10V1000U±20%8×16 3.5	4	TC505,TC506,TC509,TC510
	22.1	CD	CD11 10V1000U±20%8×14 3.5	4	TC505,TC506,TC509,TC510
	22.2	CD	GS 10V1000U±20%8×16 3.5	4	TC505,TC506,TC509,TC510
	22.3	CD	GS 10V1000U±20%8×14 3.5	4	TC505,TC506,TC509,TC510
23		CD	LP3 400V47U±20%22×28 10	1	TC501
	23.1	CD	LS 400V47U±20%22×25 10	1	TC501
24		MAGNETIC BEADS INDUCTOR	RH354708	1	L503
25		CHOKE COIL	VERTICAL 10UH 1A 5mm	1	L505
26		CHOKE COIL	VERTICAL 10UH 2A 5mm	2	L506,L507
27		SWITCHING POWER TRANSFORMER	BCK-28-0286	1	T501
	27.1	SWITCHING POWER TRANSFORMER	BCK2801-624	1	T501
28		DIODE	HER105	4	D506,D508,D511,D512
29		DIODE	HER306	1	D510
30		SCHOTTKY DIODE	SR360	1	D509
31		DIODE	HER107	1	D505
32		VOLTAGE REGULATOR DIODE	5.1V 1/2W	1	ZD501
33		VOLTAGE REGULATOR DIODE	9.1V 1W	1	ZD502
34		DIODE	1N4007	4	D501~D504
35		IC	5L0380R YDTU	1	U501
36		IC	LM431ACZ TO-92	1	U503
	36.1	IC	TL431C TO-226AA(LP)	1	U503
	36.2	IC	431L TO-92	1	U503
	36.3	IC	KA431AZ TO-92	1	U503

37		POWERGRID FILTER	UT-20 40mH $\pm 20\%$ 10×13	1	L501
38		PHOTOELECTRIC COUPLER	HS817	1	U502
39		IC	LM7805 GOLD SEALED TO-220	1	U504
40		PCB	5933-0	1	
41		SOCKET	5P 2.0mm	1	CN501
42		SOCKET	9P 2.5mm	1	CN503
43		SOCKET	2P 2.5mm	1	CN502
44		SOCKET	6P 2.5mm	1	CN504
45		SOCKET	2P 8.0mm 2#	2	BCN501,BCN502
46		CONNECTION CORDS	$\Phi 0.6$ SHAPED 7.5mm	2	J506,J503
47		CONNECTION CORDS	$\Phi 0.6$ SHAPED 10mm	4	L502,J501,J505
48		CONNECTION CORDS	$\Phi 0.6$ SHAPED 12.5mm	2	J504,J502
49		FUSE	T1.6AL 250V	1	F501
50		FUSE HOLDER	BLX-2	1	FOR F501
51		HEAT RADIATION BOARD	11×15×25 AB009K	2	U501,U504 FOR HEAT RADIATION
	51.1	HEAT RADIATION BOARD	11×15×25 WHITE AB905	2	U501,U504 FOR HEAT RADIATION
52		GROUND CHIP OF POWER BOARD	AB903	2	G501~G502
53		TAPPING SCREW	BT 3×8 BLACK	2	FIXED HEAT RADIATION

3. MAIN FRONT PANEL

NO		MATERIAL	SPECIFICATIONS/PART NUMBER	QUANTITY	LOCATION
1		SOFT SPONGE SPACER	15×7×3.5 DOUBLE FACED HARD	3	CONNECT VFD WITH FRONT PANEL PCB
2		SOFT SPONGE SPACER	12×10×6.5 DOUBLE FACED HARD	1	CONNCTC IR SENSOR WITH FRONT PANEL PCB
3		CARBON FILM RESISTOR	1/4W10 $\Omega \pm 5\%$ SHAPED 10	1	R418
	3.1	CARBON FILM RESISTOR	1/4W10 $\Omega \pm 5\%$	1	R418
4		CARBON FILM RESISTOR	1/4W100 $\Omega \pm 5\%$	1	R415
	4.1	CARBON FILM RESISTOR	1/4W100 $\Omega \pm 5\%$ SHAPED 10	1	R415
5		CARBON FILM RESISTOR	1/4W10K $\pm 5\%$	7	R406~R410,R416,R417
	5.1	CARBON FILM RESISTOR	1/4W10K $\pm 5\%$ SHAPED 10	7	R406~R410,R416,R417
6		CARBON FILM RESISTOR	1/4W51K $\pm 5\%$	1	R405
7		CARBON FILM RESISTOR	1/4W33K $\pm 5\%$	8	R401~R404,R411~R414
8		PORCELAIN CAPACITOR	50V 103 $\pm 10\%$ 5mm	2	C401,C405
9		CD	CD11C 10V100U $\pm 20\%$ 5×7 2	2	C402,C407
10		DIODE	1N4148	2	D401, D402
11		IC	D16312GB QFP	1	U401
	11.1	IC	PT6312LQ QFP	1	U401
12		VFD	HNV 06SS98	1	VFD401
13		LIGHT TOUCH RESTORE SWITCH	HORIZONTAL 6×6×1	6	K401~K406
14		PCB	4933-0	1	
15		CONNECTION CORDS	$\Phi 0.6$ SHAPED 10mm	8	JP404~JP411
16		CONNECTION CORDS	$\Phi 0.6$ SHAPED 7.5mm	3	JP401~JP403

17		FLAT CABLE	5-6P120 2.0 2 SOCKET WITH L NEEDLE REVERSE 5 CORD	1	XS402
18		FLAT CABLE	5P150 2.0 2 SOCKET WITH L NEEDLE REVERSE	1	XS401
19		IR SENSOR	HS0038A2	1	U403

4. OK BOARD

NO		MATERIAL	SPECIFICATIONS/PART NUMBER	QUANTITY	LOCATION
1		CARBON FILM RESISTOR	1/6W1K±5%	1	R619
2		SMD RESISTOR	1/16W 1K ±5%	4	R607,R608,R611, R626
3		CARBON FILM RESISTOR	1/6W4.7K±5%	2	R622,R628
4		SMD RESISTOR	1/16W 5.6K ±5%	1	R616
5		SMD RESISTOR	1/16W 10K ±5%	6	R606,R617,R620,R621,R624, R605
6		CARBON FILM RESISTOR	1/6W10K±5%	1	R612
7		CARBON FILM RESISTOR	1/4W10Ω±5%	2	R632 R633
8		CARBON FILM RESISTOR	1/6W15K±5%	1	R614
9		SMD RESISTOR	1/16W 15K ±5%	1	R618
10		SMD RESISTOR	1/16W 18K ±5%	1	R615
11		SMD RESISTOR	1/16W 22K ±5%	2	R601 R602
12		SMD RESISTOR	1/16W 27K ±5%	1	R629
13		SMD RESISTOR	1/16W 30K ±5%	3	R609 R610 R613
14		SMD RESISTOR	1/16W 560Ω ±5%	2	R603 R604
15		SMD RESISTOR	50V104 ±20% 0603	7	C609 C601 C602 C613 C614 C622 C623
16		CD	CD11 16V4.7U±20%5×11 2	9	TC601 TC602 TC603 TC604 TC607 TC613 TC621 TC610
17		CD	CD11 16V22U±20%5×11 2	2	TC605 TC606
18		CD	CD11 16V47U±20%5×11 2	1	TC609
19		CD	CD11 25V100U±20%6×12 2.5	3	TC608 TC615 TC616
20		SMD CAPACITOR	50V 101 ±5% NPO 0603	4	C605 C606 C607 C620
21		SMD CAPACITOR	50V 102 ±10% 0603	1	C619
22		SMD CAPACITOR	50V 103 ±10% 0603	3	C603 C604 C616
23		SMD CAPACITOR	50V 392 ±10% 0603	2	C608 C615
24		SMD CAPACITOR	50V 561 ±10% 0603	2	C610 C612
25		MAGNETIC BEADS INDUCTOR	RH354708	2	L601 L602
26		FLAT CABLE	6P80 2.5 2 SOCKET WITH NEEDLE	1	XS601
27		MICROPHONE SOCKET	CK3-6.35-106	2	MIC601 MIC602
28		ROTATED POTENTIOMETER	A091NOXA-V1B103-003	1	VR601
	28.1	ROTATED POTENTIOMETER	W109-1A-B10K-F20	1	VR601
29		ROTATED POTENTIOMETER	A091NOXA-V1B503-003	1	VR602
	29.1	ROTATED POTENTIOMETER	W109-1A-B50K-F20	1	VR602

30		IC	RC4558P DIP	2	U601 U602
31		IC	PT2399 DIP	1	U603
32		CONNECTION CORDS	Φ0.6 SHAPED 7.5mm	2	JP601,JP602
33		PCB	6920S-0	1	

5. OUTPUT BOARD

NO		MATERIAL	SPECIFICATIONS/PART NUMBER	QUANTITY	LOCATION
1		CARBON FILM RESISTOR	1/4W68Ω±5%	1	R703
2		CARBON FILM RESISTOR	1/6W100Ω±5%	1	R702
3		CARBON FILM RESISTOR	1/4W220Ω±5%	1	R701
4		CARBON FILM RESISTOR	1/4W330Ω±5%	1	R709
5		SMD RESISTOR	1/16W 2.2Ω ±5%	1	R706
6		CARBON FILM RESISTOR	1/6W1K±5%	1	R711
7		CARBON FILM RESISTOR	1/4W33Ω±5%	1	R708
8		CARBON FILM RESISTOR	1/6W2.2K±5%	2	R710,R712
9		SMD RESISTOR	1/16W 4.7K ±5%	1	R704
10		SMD RESISTOR	1/16W 75Ω ±5%	1	R705
11		SMD CAPACITOR	50V 102 ±10% 0603	3	C701~C703
12		SMD CAPACITOR	16V 105 +80%-20% 0603	1	C707
13		SMD CAPACITOR	50V 104 +80%-20% 0603	1	C704
14		SMD CAPACITOR	50V 104 ±20% 5mm	3	C705,C706,C713
	14.1	PORCELAIN CAPACITOR	50V 104 +80%-20% 5mm	3	C705,C706,C713
15		TRIODE	S8050D	3	V701~V703
16		CD	CD11 16V220U±20%6×12 2.5	5	TC701,TC705,TC706,TC708,TC709
17		CD	GS 10V1000U±20%8×14 3.5	1	TC707
	17.1	CD	CD11 10V1000U±20%8×14 3.5	1	TC707
	17.2	CD	GS 10V1000U±20%8×16 3.5	1	TC707
	17.3	CD	CD11 10V1000U±20%8×16 3.5	1	TC707
17		MAGNETIC BEADS INDUCTOR	RH354708	9	L701,L702,L703,L707~L712
18		ELECTRO-OPTIC TRANSFORMER	TP01A	1	JK704
	18.1	ELECTRO-OPTIC TRANSFORMER	TX179AT	1	JK704
19		TERMINAL SOCKET	CS-09	1	JK702
20		SCART SOCKET	SCART-01	1	JK705
21		CABLE SOCKET	14P 1.0mm STRAIGHT DUAL LINE PLUG	1	XS701
21		TERMINAL SOCKET	AV4-8.4-6G-3	1	JK703
23		TERMINAL SOCKET	AV4-8.4-13/PB-08	1	JK701
25		CONNECTION CORDS	Φ0.6 SHAPED 5mm	8	JP701,JP702,JP704,JP706~JP710
26		CONNECTION CORDS	Φ0.6 SHAPED 10mm	2	R707,JP703
27		CONNECTION CORDS	Φ0.6 SHAPED 7.5mm	1	JP705
24		PCB	7920S-0	1	